

# TECHNICAL REPORT

**IEC**  
**TR 62380**

First edition  
2004-08

---

---

**Reliability data handbook –  
Universal model for reliability prediction  
of electronics components, PCBs  
and equipment**

IECNORM.COM: Click to view the full PDF of IEC/TR 62380:2004



Reference number  
IEC/TR 62380:2004(E)

## Publication numbering

As from 1 January 1997 all IEC publications are issued with a designation in the 60000 series. For example, IEC 34-1 is now referred to as IEC 60034-1.

## Consolidated editions

The IEC is now publishing consolidated versions of its publications. For example, edition numbers 1.0, 1.1 and 1.2 refer, respectively, to the base publication, the base publication incorporating amendment 1 and the base publication incorporating amendments 1 and 2.

## Further information on IEC publications

The technical content of IEC publications is kept under constant review by the IEC, thus ensuring that the content reflects current technology. Information relating to this publication, including its validity, is available in the IEC Catalogue of publications (see below) in addition to new editions, amendments and corrigenda. Information on the subjects under consideration and work in progress undertaken by the technical committee which has prepared this publication, as well as the list of publications issued, is also available from the following:

- **IEC Web Site** ([www.iec.ch](http://www.iec.ch))

- **Catalogue of IEC publications**

The on-line catalogue on the IEC web site ([www.iec.ch/searchpub](http://www.iec.ch/searchpub)) enables you to search by a variety of criteria including text searches, technical committees and date of publication. On-line information is also available on recently issued publications, withdrawn and replaced publications, as well as corrigenda.

- **IEC Just Published**

This summary of recently issued publications ([www.iec.ch/online\\_news/justpub](http://www.iec.ch/online_news/justpub)) is also available by email. Please contact the Customer Service Centre (see below) for further information.

- **Customer Service Centre**

If you have any questions regarding this publication or need further assistance, please contact the Customer Service Centre:

Email: [custserv@iec.ch](mailto:custserv@iec.ch)  
Tel: +41 22 919 02 11  
Fax: +41 22 919 03 00

# TECHNICAL REPORT

# IEC TR 62380

First edition  
2004-08

---

---

## Reliability data handbook – Universal model for reliability prediction of electronics components, PCBs and equipment

© IEC 2004 — Copyright - all rights reserved

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembe, PO Box 131, CH-1211 Geneva 20, Switzerland  
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: [inmail@iec.ch](mailto:inmail@iec.ch) Web: [www.iec.ch](http://www.iec.ch)



Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

PRICE CODE **XC**

*For price, see current catalogue*

## CONTENTS

|   |    |
|---|----|
| FOREWORD .....  | 5  |
| INTRODUCTION .....  | 7  |
| 1 Scope .....   | 8  |
| 2 Normative references .....  | 8  |
| 3 Terms and definitions .....   | 9  |
| 4 Conditions of use .....   | 10 |
| 4.1 Introductory remarks .....  | 10 |
| 4.2 Assumptions adopted for TR 62380 .....  | 11 |
| 4.3 Influencing factors .....   | 13 |
| 4.4 How to use the data .....   | 14 |
| 4.5 Uses and aims of a reliability prediction .....   | 15 |
| 5 Environment influence .....   | 16 |
| 5.1 General remarks .....   | 16 |
| 5.2 Environment types defined .....   | 16 |
| 5.3 Electrical environment conditions .....   | 20 |
| 5.4 Validity model according to environment .....   | 20 |
| 5.5 Components choice .....   | 20 |
| 5.6 Learning during the deployment phase of new equipment .....   | 21 |
| 5.7 Mission profile .....   | 22 |
| 5.8 Mission profile examples .....  | 23 |
| 6 Equipped printed circuit boards and hybrid circuits (IEC 60326) .....   | 25 |
| 6.1 Failure rate calculation of an equipped printed circuit board .....   | 25 |
| 6.2 Hybrid circuits .....   | 26 |
| 7 Integrated circuits .....   | 27 |
| 7.1 Validity domain .....   | 27 |
| 7.2 Junction temperature evaluation of an integrated circuit .....  | 27 |
| 7.3 The reliability model .....   | 30 |
| 8 Diodes and thyristors, transistors, optocouplers (IEC 60747-xx) .....   | 36 |
| 8.1 Evaluating the junction temperature of diodes and transistors .....   | 36 |
| 8.2 Low power diodes .....  | 38 |
| 8.3 Power diodes .....  | 40 |
| 8.4 Low power transistors .....   | 42 |
| 8.5 Power transistors .....   | 44 |
| 8.6 Optocouplers .....  | 46 |
| 9 Optoelectronics .....   | 49 |
| 9.1 Light emitting diodes diode modules (IEC 60747-12-2, IEC 62007) .....   | 49 |
| 9.2 Laser diodes modules - Failure rate .....   | 52 |
| 9.3 Photodiodes and receiver modules for telecommunications (IEC 60747-12) .....                                    | 53 |
| 9.4 Passive optic components .....  | 54 |
| 9.5 Miscellaneous optic components .....  | 54 |
| 10 Capacitors and thermistors (ntc) .....   | 55 |
| 10.1 Fixed plastic, paper, dielectric capacitors - Radio interference suppression capacitors (plastic, paper) ..... | 55 |

|      |  |    |
|------|--|----|
| 10.2 | Fixed ceramic dielectric capacitors – Defined temperature coefficient – Class I (IEC 60384)  | 56 |
| 10.3 | Fixed ceramic dielectric capacitors – Non defined temperature coefficient – Class II – Radio interference suppression capacitors (Ceramic, class II) | 57 |
| 10.4 | Tantalum capacitors, solid electrolyte (IEC 60384)   | 58 |
| 10.5 | Aluminum, non-solid electrolyte capacitors - Life expectancy   | 59 |
| 10.6 | Aluminum electrolytic capacitor, solid electrolyte   | 61 |
| 10.7 | Aluminum electrolytic capacitor, polymer electrolyte (IEC 60384)   | 62 |
| 10.8 | Variable ceramic capacitors, disks (Dielectric ceramic) (IEC 60384)  | 63 |
| 10.9 | Thermistors with negative temperature coefficient (NTC) (IEC 60539)  | 64 |
| 11   | Resistors and potentiometers (IEC 60115)   | 65 |
| 11.1 | Fixed, low dissipation film resistors – High stability (rs), general purpose (rc), “minimelf”  | 65 |
| 11.2 | Hot molded carbon composition, fixed resistors (IEC 60115)   | 66 |
| 11.3 | Fixed, high dissipation film resistors (IEC 60115)   | 67 |
| 11.4 | Low dissipation wirewound resistors (IEC 60115)  | 68 |
| 11.5 | High dissipation wirewound resistors (IEC 60115)   | 69 |
| 11.6 | Fixed, low dissipation surface mounting resistors and resistive array (IEC 60115)  | 70 |
| 11.7 | Non wirewound cermet potentiometer (one or several turn) (IEC 60393)   | 71 |
| 12   | Inductors and transformers (IEC 61248)   | 73 |
| 13   | Microwave passive components, piezoelectric components and surface acoustic wave filters (IEC 61261, IEC 61019, IEC 60368)                           | 74 |
| 13.1 | Microwave passive components   | 74 |
| 13.2 | Piezoelectric components   | 74 |
| 13.3 | Surface acoustic wave filters  | 74 |
| 14   | Relays   | 75 |
| 14.1 | Evaluating voltage and current (vt, it) in transient conditions  | 75 |
| 14.2 | Mercury wetted reed relays, low power (IEC 60255)  | 78 |
| 14.3 | Dry reed relays (IEC 60255)  | 80 |
| 14.4 | Electromechanical relays, miniature or card – European type, thermal relays (power up to 500 W) (IEC 60255)  | 82 |
| 14.5 | Industrial relays, high voltage vacuum relays, power mercury wetted relays (IEC 60255)   | 84 |
| 15   | Switches and keyboards (IEC 60948)   | 86 |
| 16   | Connectors   | 87 |
| 16.1 | Circular, rectangular  | 87 |
| 16.2 | Coaxial connectors   | 87 |
| 16.3 | Connectors for PCBs and related sockets  | 87 |
| 17   | Displays, solid state lamps  | 88 |
| 17.1 | Displays (IEC 61747)   | 88 |
| 17.2 | Solid state lamps (IEC 60747)  | 88 |
| 18   | Protection devices (IEC 60099, IEC 60269, IEC 60738, IEC 61051)  | 89 |
| 18.1 | Thermistors (PTC)  | 89 |
| 18.2 | Varistors  | 89 |
| 18.3 | Fuses  | 89 |
| 18.4 | Arrestors  | 89 |
| 19   | Energy devices, thermal management devices, disk drive   | 90 |
| 19.1 | Primary batteries  | 90 |
| 19.2 | Secondary batteries  | 90 |

|  |    |
|--|----|
| 19.3 Fans .....  | 90 |
| 19.4 Thermoelectric coolers .....  | 90 |
| 19.5 Disk drive .....  | 90 |
| 19.6 Converters (IEC 60146).....   | 90 |
| Table 1 – Mission profiles for spatial.....  | 10 |
| Table 2 – Mission profiles for military.....   | 10 |
| Table 3 – Description and typical applications of the commonest types of environment .....   | 17 |
| Table 4 – Mechanical conditions according to the environment: characteristic shocks and vibrations.....  | 18 |
| Table 5 – Mechanically active substances.....  | 19 |
| Table 6 – Chemically active substances.....  | 19 |
| Table 7 – Typical conditions for each environment type according to Table 3 (mechanically and chemically active substances and climatic conditions) .....          | 19 |
| Table 8 – Table of climates.....   | 23 |
| Table 9 – Mission profiles for Telecom.....  | 23 |
| Table 10 – Mission profiles for military and civil avionics .....  | 24 |
| Table 11 – Mission profiles for automotive .....   | 24 |
| Table 12 – Thermal resistance as a function of package type, the pin number and airflow factor .....   | 28 |
| Table 13 – Typical values of the air flow speed V, and the air flow factor K.....  | 29 |
| Table 14 – Thermal expansion coefficients $\alpha_s$ and $\alpha_c$ .....  | 32 |
| Table 15 – Failure distribution (for non interfaces integrated circuits) .....   | 32 |
| Table 16 – Values of $\lambda_1$ and $\lambda_2$ for integrated circuits families .....  | 33 |
| Table 17a – $\lambda_3$ values for integrated circuits as a function of S (pin number of the package).....   | 34 |
| Table 17b – $\lambda_3$ values for surface mounted integrated circuits packages as a function of D (package diagonal).....   | 35 |
| Table 18 – Values of $\lambda_B$ and junction resistances for active discrete components .....   | 37 |
| Figure 1 – Time dependant failure rate of a new electronic printed circuit board.....  | 21 |
| Figure 1 – Time-dependant failure rate of a new electronic printed circuit board .....   | 21 |
| Figure 2 – Equivalent diagram representing the circuit of a relay contact .....  | 75 |
| Figure 3 – Positions of capacitors in the real circuit diagram for which the values must be counted in C.....  | 75 |
| Figure 4 – Regions adopted for the purposes of Figures 5, 6 and 7 .....  | 76 |
| Figure 5 – Evaluating the ratios $V_t/V$ and $I_t/I$ according to $R=R_1+R_2$ , C, L, and $C_p$ , $L_p$ ( R in k $\Omega$ , C, $C_p$ in nF ; L , $L_p$ in mH)..... | 76 |
| Figure 6 – Evaluating ratios $V_t/V$ and $I_t/I$ when L and C are not known .....  | 77 |
| Figure 7 – Default values of $V_t/V$ and $I_t/I$ when nothing is known about the electrical circuit of the contact.....  | 77 |

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**RELIABILITY DATA HANDBOOK –  
UNIVERSAL MODEL FOR RELIABILITY PREDICTION  
OF ELECTRONICS COMPONENTS, PCBs AND EQUIPMENT**

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62380, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

|               |                  |
|---------------|------------------|
| Enquiry draft | Report on voting |
| 47/1705/DTR   | 47/1722A/RVC     |

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This technical report does not follow the rules for structuring international standards as given in Part 2 of the ISO/IEC Directives.

NOTE This technical report has been reproduced without significant modification to its original content or drafting.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IECNORM.COM: Click to view the full PDF of IEC TR 62380:2004

## INTRODUCTION

This reliability calculation guide for electronic and optical card, is an important progress compared to older guides. Calculation models take directly into account the influence of the environment. The thermal cycling seen by cards, function of mission profiles undergone by the equipment, replace environment factor which is difficult to evaluate. These models can handle permanent working, on/off cycling and dormant applications. On the other hand, failure rate related to the component soldering, is henceforth-included in component failure rate.

IECNORM.COM: Click to view the full PDF of IEC TR 62380:2004

# RELIABILITY DATA HANDBOOK – UNIVERSAL MODEL FOR RELIABILITY PREDICTION OF ELECTRONICS COMPONENTS, PCBs AND EQUIPMENT

## 1 Scope

This technical report provides elements to calculate failure rate of mounted electronic components. It makes equipment reliability optimization studies easier to carry out, thanks to the introduction of influence factors.

## 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60086 (all parts), *Primary batteries*

IEC 60099 (all parts), *Surge arresters*

IEC 60115 (all parts), *Fixed arrestors for use in electronic equipment*

IEC 60146, (all parts), *Semiconductor convertors – General requirements and line commutated convertors*

IEC 60255 ((all parts), *Electrical relays*

IEC 60269 (all parts), *Low-voltage fuses*

IEC 61951 (all parts), *Secondary cells and batteries containing alkaline or other non-alkaline electrolytes – Portable sealed rechargeable single cells*

IEC 60326 (all parts), *Printed boards*

IEC 60368 (all parts), *Piezoelectric filters of assessed quality*

IEC 60384 (all parts), *Fixed capacitors for use in electronic equipment*

IEC 60393 (all parts), *Potentiometers for use in electronic equipment*

IEC 60535, *Jet fans and regulators*

IEC 60539 (all parts), *Directly heated negative temperature coefficient thermistors*

IEC 60721-3 (all Parts 3), *Classification of environmental conditions – Part 3: Classification of groups of environmental parameters and their severities*

IEC 60738 (all parts), *Thermistors - Directly heated positive step-function temperature coefficient*

IEC 60747 (all parts) *Semiconductor devices - Discrete devices*

IEC 60747-12 (all Parts 12) *Semiconductor devices - Part 12: Optoelectronic devices*

IEC 60747-12-2, *Semiconductor devices – Part 12: Optoelectronic devices – Section 2: Blank detail specification for laser diode modules with pigtail for fibre optic systems and sub-systems*

IEC 60748 (all parts) *Semiconductor devices – Integrated circuits*

IEC 60879, *Performance and construction of electric circulating fans and regulators*

IEC 60948, *Numeric keyboard for home electronic systems (HES)*

IEC 61019 (all parts), *Surface acoustic wave (SAW) resonators*

IEC 61051 (all parts), *Varistors for use in electronic equipment*

IEC 61248 (all parts), *Transformers and inductors for use in electronic and telecommunication equipment*

IEC 61747 (all parts), *Liquid crystal and solid-state display devices*

IEC 61261 (all parts), *Piezoelectric ceramic filters for use in electronic equipment – A specification in the IEC quality assessment system for electronic components (IECQ)*

IEC 61951 (all parts), *Secondary cells and batteries containing alkaline or other non-acid electrolytes*

IEC 61951-1, *Secondary cells and batteries containing alkaline or other non-acid electrolytes – Portable sealed rechargeable single cells*

IEC 61951-2, *Secondary cells and batteries containing alkaline or other non-acid electrolytes – Nickel-metal hydride*

IEC 62007 (all parts), *Semiconductor optoelectronic devices for fibre optic system applications*

IEC 62255 (all parts), *Multicore and symmetrical pair/quad cables for broadband digital communications (high bit rate digital access telecommunication networks) - Outside plant cables*

ETS 300 019, *Environmental engineering (EE); Environmental conditions and environmental tests for telecommunications equipment*

ISO 9000:2000, *Quality management systems – Fundamentals and vocabulary*

UTE C 96-024:1990, *Modèles thermiques simplifiés des circuits intégrés monolithiques*

### **3 Terms and definitions**

For the purposes of this technical report, the following definitions apply.

#### **3.1**

##### **spatial**

Mission profiles corresponding to the MIL-HDBK-217F "Space; flight" environment.

NOTE Only one working phase is taken into account during each orbital revolution (LEO), or earth revolution (GEO).

**Table 1 – Mission profiles for spatial**

| Application types                                 | $(t_{ac})_1$<br>°C | $\tau_1$ | $\tau_{on}$ | $\tau_{off}$ | $n_1$<br>cycles/year | $\Delta T_1$<br>°C/orbit      |
|---|--------------------|----------|-------------|--------------|----------------------|-------------------------------|
| Low earth orbit (LEO) with On/Off cycling         | 40                 | 0,15     | 0,15        | 0,85         | 5256                 | $\frac{\Delta T_{je}}{3} + 7$ |
| Low earth orbit (LEO) permanent working           | 40                 | 1        | 1           | 0            | 5256                 | 3                             |
| Geostationary earth orbit (GEO) permanent working | 40                 | 1        | 1           | 0            | 365                  | 8                             |

**3.2 military**

Mission profiles corresponding to the MIL-HDBK-217F "Ground; mobile" environment.

NOTE Two working phases are taken into account:

Phase 1: 36 annual switch on

Phase 2: 365 days of dormant mode

**Table 2 – Mission profiles for military**

| Application type | $(t_{ac})_1$<br>°C | $\tau_1$ | $\tau_{on}$ | $\tau_{off}$ | $n_1$<br>cycles/year | $\Delta T_1$<br>°C/cycle    | $n_2$<br>cycles/year | $\Delta T_2$<br>°C/cycle |
|------------------|--------------------|----------|-------------|--------------|----------------------|-----------------------------|----------------------|--------------------------|
| Portable Radio   | 26                 | 0,01     | 0,01        | 0,99         | 36                   | $\frac{\Delta T_j}{3} + 15$ | 365                  | 8                        |

**4 Conditions of use**

**4.1 Introductory remarks**

**4.1.1 Theory of reliability predictions**

Calculation of a reliability prediction for non-redundant equipment is the very first step in any complete reliability study concerning that equipment, and indeed, of any study of the reliability, availability, or safety of a system.

Reliability predictions are based on numerous assumptions, all of which need to be verified (choice of component family, for example).

A reliability study of an item entails not only verifying these assumptions, but also optimizing its reliability (qualification of components and mounting processes, minimizing risk of external failure, etc).

A reliability prediction is essential, but no more so than research into the best possible reliability for least cost.

This handbook provides all the information needed to calculate electronic component and equipped printed circuit board failure rates: failures rates delivered include the influence of component mounting processes.

**4.1.2 Structure of the handbook**

The handbook is specifically designed as an aid to research into how to maximize equipment reliability, and to assist in the design of the equipment, by introducing various influencing factors (see also 4.3). In order to meet this objective, it is important that any reliability prediction should begin with the start of design (and then be finalised in accordance with 4.5.4). Similarly, the choice of values for the influencing factors should not be automatic.

### 4.1.3 Data source

The reliability data contained in the handbook is taken mainly from field data concerning electronic equipment operating in four kinds of environment:

- a) «Ground; stationary; weather protected» (in other words: equipment for stationary use on the ground in weather protected locations, operating permanently or otherwise).

This applies mainly to telecommunications equipment and computer hardware.

- b) «Ground; stationary; non weather protected» (in other words: equipment for stationary use on the ground in non-weather protected locations).

This relates mainly to public payphones and GSM relays.

- c) «Airborne, Inhabited, Cargo» (in other words: equipment used in a plane, benign conditions).

This relates to on board calculators civilian planes.

- d) «Ground; non stationary; moderate» (in other words: equipment for non-stationary use on the ground in moderate conditions of use).

This concerns mainly on board automotive calculators and military mobile radio.

By processing the raw data (statistical processes, results based on geographic distribution, according to equipment type, etc.), it has been possible to include various influencing factors and eliminate the main aberrant values. Other influencing factors are derived from the experience of experts (failure analyses, construction analyses, results of endurance tests).

The values adopted are those considered most probable at the present time (1992-2001).

This databook does not give any part count values, because mission profiles are needed in order to have credible values.

## 4.2 Assumptions adopted for TR 62380

### 4.2.1 Nature of data

#### 4.2.1.1 Reliability data

The reliability data in this handbook comprises failure rates and, for some (very few) component families, life expectancy.

Failure rates are assumed to be constant either for an unlimited period of operation (general case) or for limited periods: in these particular cases the laws governing failure rates versus time have not been adopted in the interests of simplicity.

Apart from a few exceptions (see section 4.2.1.3), the wear-out period is never reached by electronic components; in the same way it is accepted, again apart from some exceptions (see section 4.2.1.2), that the added risks of failure during the first few months of operation can be disregarded.

#### 4.2.1.2 The infant mortality period

In practice, except for a few component families, the increased risk of failure during the first months of operation can be disregarded, because of the diversity of reasons for variations or uncertainty in the failure rate. This superficially simplistic hypothesis is in fact very realistic. It is confirmed by field data concerning the operation of equipment designed very carefully, with well chosen components (based on compatibility with use) and produced by a well controlled production system, as is generally the case for the components covered by this handbook.

### 4.2.1.3 Wear-out period

For the vast majority of components, the -wear-out period (during which failures take on a systematic character) is far removed from the periods of use (which range from 3 to 20 years).

There are, however, two cases in which the occurrence of wear-out failures should be taken into account (the failure rate of which increases with time):

- a) For some families, if due care is not taken, the wear-out mechanisms may give rise to systematic failures after too short a period of time; metallization electromigration in active components, for example.

This risk needs to be eliminated by a good product design, and it is important to ensure this by qualification testing. In other words, it should not be taken into account for a prediction, and should be eliminated by qualification testing and by technical evaluation, which are, therefore, of critical importance.

- b) For some (few) component families, the wear-out period is relatively short. For these families, this handbook explains how to express the period for which the failure rate can be considered constant. This life expectancy is subject to influencing factors.

Such families include relays, aluminium capacitors (with non-solid electrolyte), laser diodes, optocouplers, power transistors in cyclic operation, connectors and switches and keyboards.

For these component families, it is important to ensure that the life expectancy given by the handbook is consistent with the intended use. If not, room for manoeuvring is fairly restricted: you can reduce the stresses, change the component family (or sub-family: for aluminium capacitors with non-solid electrolyte, there are several types characterized by different qualification tests).

Provision can also be made for preventive maintenance.

NOTE: As before, and in the interests of simplicity, this handbook does not give the wear-out failure mathematical model (for which the failure rate increases over time), but a period during which the rate can be considered constant (in some cases the period at 10% of the cumulative failure rate).

## 4.2.2 Nature of failures

### 4.2.2.1 Intrinsic failures

The data in this handbook covers intrinsic failures (apart from the few exceptions given in 4.2.2.2).

In practice (see section 4.1.3), the raw reliability data has been processed to eliminate non-intrinsic component failures.

### 4.2.2.2 Special case of non-intrinsic residual failures due to electrical overloads

There is, necessarily, a small proportion of non-intrinsic failures in the data, because it is impossible to detect all the non-intrinsic failures when they are residual.

Take, for example, the reliability of the components used in equipment located “at the heart” of a system, which is significantly better than that of the components located at the periphery (in other words connected to the external environment). It is understood that this is due to residual overloads, since the equipment is assumed adequately protected.

For the purpose of this handbook, we have therefore included an utilisation factor to take into account nonintrinsic residual failures due to the electrical environment for active components.

### 4.2.2.3 Other non-intrinsic failures

The other non-intrinsic failures (due to errors of design, choice, uses) are excluded from this handbook.

Errors of this kind should be avoided; hence they are not taken into for predictions. As a matter of fact, they are very largely independent of component family.

However, for some particular objectives, such as calculation of stocks of spare parts, it may be useful to include the risks of non-intrinsic residual failures due to design errors: some indications are given in section 4.4.3.

### 4.2.3 Large-scale integrated circuit, production date influence

Since the 90's, the reliability growth of components no longer occur, as in the 70's and the 80's; thanks to fields failures returns data collections. This is particularly true for integrated circuits, and can be attributed to: generalization of nitride based passivations, generalization of dry etching and better planarization controls. However, the integration density for integrated circuits continues to grow at the same rate as in the past, at a constant reliability figure. For this reason, and in order to takes into account the Moore law, it is necessary to know the manufacturing year to calculate the failure rate of integrated circuits.

## 4.3 Influencing factors

### 4.3.1 Component failure rate

The component failure rate depends on a number of operational and environmental factors. This is why, for each component family, the handbook gives a base failure rate value (normally a value which corresponds to the commonest internal temperature taken as a reference) multiplied by a number of influencing factors. This simplified, empirical expression takes account of the more significant influencing factors when it comes to conditions of use.

The main factors adopted are as follows:

a) Factors giving the influence of temperature ( $\pi_t$ ,  $\pi_w$ )

It is now widely accepted that temperature has a moderate effect on component reliability. The effect is significant for some families (active components and aluminum capacitors with non-solid electrolyte). The models adopted are those which give the effect of temperature on the predominating failure mechanisms (which are not normally the "wear-out" mechanisms).

For semiconductors, an Arrhenius equation has been applied with activation energy of 0.3 to 0.4 electron volts.

For passive components, an Arrhenius equation has been applied with an activation energy of 0.15 to 0.4 electron volts.

Factor  $\pi_w$  for potentiometers gives the influence of load resistance on the temperature rise.

In the case of power dissipating components, the thermal resistance (semiconductors) or the equation giving the internal temperature as a function of ambient temperature (resistors) has been given.

b) Factors giving the influence of special stresses:

Utilization factor  $\pi_u$  for thyristors, Zener diodes (operating permanently powered or otherwise).

Factor  $\pi_A$  for Aluminum liquid electrolyte capacitors giving the effect of current pulses.

Factor  $\pi_Y$  for relays (operating cycle rate).

Factor  $\pi_i$  for connectors (current intensity).

c) Factors giving the influence of applied voltage ( $\pi_s$ ).

The influence of applied voltage is taken into account for transistors and optocouplers (voltage applied between input and output).

#### 4.3.2 Life expectancy

Life expectancy, when limited, is also influenced by certain factors (optocoupler operating current; temperature of aluminum capacitors with non-solid electrolyte; contact current for relays).

Life expectancy can be expressed as a number of cycles (power transistors, switches).

### 4.4 How to use the data

#### 4.4.1 Calculation method

Given that the component failure rates are assumed constant, the failure rate of a non-redundant equipment can be obtained by adding together the failure rates of its individual components. In this handbook, the failure rates given for components include the effects of the mounting on a printed circuit board, the failure rate of the naked PCB or hybrid has to be added.

Clause 6 of this handbook explains the method to be used to calculate the failure rate of a printed circuit board or a hybrid.

#### 4.4.2 Reliability prediction results

The results of a reliability prediction are many and various, and not limited to failure rate: the following information is also obtained:

- Failure rate (of component or equipment).
- Choice of technical construction for some components (choice of component family).
- Choice of conditions of use.

#### 4.4.3 Failure rate

The failure rate can be used directly if the aim is to identify a reference base. Such is the case for many objectives described in 4.5.

However, if the aim is to obtain an accurate estimate of stocks of spare parts, the result should be updated to take account of non-intrinsic failures:

- unconfirmed failure phenomena (equipment, subsystem, identified as defective and found to be OK on repair);
- incorrect component usage, wrong choice of components for the first months of use of equipment of new design (period of improving reliability);
- incorrect maintenance, inappropriate use, human error, environmental attack;
- production process learning factor (component mounting process, etc).

The appropriate uprating factors cannot be given in this handbook: they depend on the prior experience of a company and how new the equipment production process is (for example, for unconfirmed failures, the uprating factor ranges from 10% to over 100%, depending on newness).

#### **4.4.4 In cases where conditions are not yet known default conditions can be assumed.**

According to 4.5.1, reliability prediction calculations should begin as early as possible, at the start of the equipment design phase, even if not all the applicable conditions can yet be known: in this case default values can be used provisionally, to help determine those conditions which are as yet unknown. These default values will then be gradually discarded as the definitive conditions are identified.

This method is far preferable to the simplified calculation method (for which all the values are replaced by default values, including those, which are already known).

The calculations must therefore be prepared in such a way as to enable values to be modified easily.

### **4.5 Uses and aims of a reliability prediction**

#### **4.5.1 Reliability prediction as an aid to equipment design**

The most beneficial use of a reliability prediction is as an aid to equipment designers. In this case, the help is based on determination of the stresses and factors influencing the reliability of each component (temperature, input voltage, technical construction of the components, etc.). Predictions based on this handbook will lead the originators of a new design to choose the best conditions and the best component families, and to draw up component qualification or evaluation programmes.

If this important objective is to be met, it is essential for the reliability prediction to be begun at the very start of design, by the design originators, and then revised as required. The work should be carried out in close collaboration with the company's component quality experts.

#### **4.5.2 Reliability prediction to assess the potential of new equipment**

The predicted reliability can be compared with the reliability objectives or stated requirements.

#### **4.5.3 Predicted reliability values as a basis for contractual reliability values**

The contractual value of a failure rate must be determined on the basis of the predicted value; these two values will not necessarily be equal: a number of contractual values may be assumed depending on observation period or certain data may be modified provided it is justified. However, in all cases, the predicted value should be taken as the base.

**4.5.4** Where used in conjunction with other characteristics of a project (electrical characteristics, weight, etc.), the results of a reliability prediction can be used to compare different project solutions, such as when evaluating proposals from tenderers. Comparisons of this kind are possible only if the data used is the same, hence the existence of a reliability data handbook.

**4.5.5** The predicted failure rates for the individual items of a system are crucial when calculating system dependability and reparability.

**4.5.6** Reliability predictions can be used as a basis for evaluating stocks of equipment and spare components required for maintenance (however, in this case, it is important to take account of probable non-intrinsic failures, as was explained in 4.4.3). The purpose of a study of this kind is to optimize stocks of spare parts (avoid stock outages, but also avoid excessive and costly stocking levels).

**4.5.7** Reliability predictions can be used as a benchmark for assessing results observed in operation. Indeed, observed results cannot be assessed effectively without a benchmark: mediocre reliability would be considered normal and there would be no attempt at improvement.

Obviously we should not expect observations to mirror exactly the predicted reliability values, for a number of reasons:

- Predictions are based only on intrinsic reliability; they do not therefore take account of external overload conditions (however, according to 4.2.2, they do take account of residual overloads).
- Predictions do not take account of design errors or incorrect use of components.
- Predictions do not take account of the risks involved in using lots of components with poor reliability.

These departures from reality, far from being a handicap are in fact an advantage; in practice, the differences can be used to reveal a lack of reliability and, following analysis, take corrective action. This very important quality enhancement process is crucial when it comes to minimizing the infant mortality period and correcting equipment design errors.

## **5 Environment influence**

### **5.1 General remarks**

Experience has shown that component reliability is heavily influenced by mechanical and climatic environment conditions, as well as by electrical environment conditions (residual overload).

This factor is therefore included in this handbook, based on observations and published values; for simplicity, climatic and mechanical environment conditions have been classified in ten or so environment types. However, the mission profile has to be taken into account (see 5.7), to determine estimated failure rate of components in the considered environment.

### **5.2 Environment types defined**

The environment types are based on IEC 60721-3 («classification of groups of environmental parameters and their severity»), with some simplifications, and the specification ETS 300 019 (ETSI specification: environmental conditions for telecommunications equipment).

Table 3 gives, for the various types of environment adopted for the purposes of this handbook, the following information:

- the short form designation adopted for this handbook;
- the complete designation (generally according to IEC 60721-3);
- the main stresses included;
- some typical applications.

Table 4 quantifies the mechanical stresses (shock and vibration) for the main types of environment.

Tables 5 define the environmental conditions according to the presence and activity of chemical and mechanical substances (definitions given in table 7 based on the conventions summarized in Tables 5 and 6), and according to climatic conditions.

**Table 3 – Description and typical applications of the commonest types of environment**

| Environment description                          |  | Description of the environment  | Applications   |
|--|--|---|--|
| Short form designation (adopted in the handbook) | Complete designation   |   |  |
| Ground; stationary; weather protected            | Equipment for <u>stationary</u> use on the <u>ground</u> in Weather protected locations  | Controlled temperature and humidity, low stress good maintenance  | Equipment in environmentally controlled premises   |
| Ground; stationary non weather protected         | Equipment for stationary use on the ground; in non Weather protected locations   | Some mechanical and climatic stresses (moderate) Average quality maintenance  | Equipment located in premises with little or no environmental control:<br>- phone booths<br>- equipment in public buildings<br>- equipment in streets, stations, etc,<br>- equipment in industrial environments. |
|  | <b>important note:</b> the phrase "non weather protected" (according to IEC 60721-3) applies to the equipment and not to the components. With regard to, the components (which are protected from the elements), the main difference from the type "ground; fixed; protected" lies in the absence of environmental control (humidity and temperature). |   |  |
| Ground; non stationary; benign                   | Equipment for <u>non-stationary</u> use on the <u>ground</u> , in <u>benign</u> conditions   | Mechanical stress is more severe than for "ground; stationary; non Weather protected" Sometimes difficult maintenance | Radiotelephones - Portable equipment on ground vehicles.<br>Railway rolling Stock equipment  |
| Ground; non stationary; severe                   | Equipment for <u>non-stationary</u> use on the <u>ground</u> , in <u>severe</u> conditions   | As for "ground; non stationary benign", but with more severe; mechanical stresses                                     |  |
| Satellite; flight                                | Used on board an orbiting satellite  | Very low mechanical stresses  |  |
| Satellite; launch                                | Used on board a satellite  | Extremely severe shock  |  |
|  | During launch  | High amplitude vibration and high frequencies (up to 2 000 Hz)  |  |
| Airborne; benign                                 | Used in an aircraft in ...   | benign conditions   | Other applications (other than "aircraft" and "ship") are possible, provided that the stresses are comparable.   |
| Airborne; moderate                               |  | moderate conditions   |  |
| Airborne; severe                                 |  | severe conditions   |  |
| Airborne; extremely severe                       |  | extremely severe conditions   |  |
| Naval; benign                                    | Used on board a ship in ...  | benign conditions   |  |
| Naval; severe                                    |  | severe conditions   |  |

**Table 4 – Mechanical conditions according to the environment: characteristic shocks and vibrations.**

| VIBRATIONS                             |  |                                     |                                      |   |                            |     |                                    |     |      |      | SHOCKS                                |                |
|--|--|-------------------------------------|--------------------------------------|---|----------------------------|-----|------------------------------------|-----|------|------|---------------------------------------|----------------|
| Accelerations<br>m/s <sup>2</sup><br>↓ | Frequencies<br>Some Hz up to the above frequency.<br>(Hz)<br>↓ | 50                                  | 100                                  | 200                                     | 200                        | 300 | 300                                | 500 | 1000 | 2000 | peak acceleration<br>m/s <sup>2</sup> | Duration<br>ms |
|  |  | 22                                  | 11                                   | 6                                       | 11                         | 6   | 11                                 | 2,3 | 6    | 0,5  |                                       |                |
| 1                                      | 200  | Ground stationary Weather-protected |                                      |   |                            |     |                                    |     |      |      |                                       |                |
| 10                                     | 200  |                                     |                                      | Ground stationary Non weather protected |                            |     |                                    |     |      |      |                                       |                |
| 20                                     | 200  |                                     | ← Naval ; benign →                   |   |                            |     |                                    |     |      |      |                                       |                |
| 20                                     | 500  |                                     | ← Ground ; non stationary ; benign → |   |                            |     |                                    |     |      |      |                                       |                |
| 20                                     | 2000   |                                     | Airborne ; benign                    |   |                            |     |                                    |     |      |      |                                       |                |
| 30                                     | 500  |                                     |                                      |   |                            |     | ← Ground; non stationary; severe → |     |      |      |                                       |                |
| 30                                     | 2000   |                                     | Airborne; moderate                   |   |                            |     |                                    |     |      |      |                                       |                |
| 50                                     | 200  |                                     | ← Naval severe →                     |   |                            |     |                                    |     |      |      |                                       |                |
| 80                                     | 2000   |                                     |                                      |   | Airborne; severe           |     |                                    |     |      |      |                                       |                |
| 150                                    | 2000   |                                     |                                      |   | Airborne; extremely severe |     |                                    |     |      |      | Satellite launch                      |                |

Tables 5 and 6: Represent the definition of concentration classes used in Table 7 for active substances

**Table 5 – Mechanically active substances**

| Designation of classes used in Table 7 | Sand (Mg/M3) | Dust    |           | Examples of type of environment |
|--|--------------|---------|-----------|---------------------------------|
|  |              | (Mg/M3) | (Mg/M2 h) |                                 |
| Negligible                             | 0            | 0,01    | 0,4       | Naval; benign                   |
| Low                                    | 30           | 0,2     | 1,5       | Ground; weather protected       |
| Moderate                               | 300          | 0,4     | 1,5       | Ground; non weather protected   |
| High                                   | 3000         | 4       | 40        | Ground; non stationary; severe  |

**Table 6 – Chemically active substances**

| Designation of classes used in Table 7 | Salt mist   | S0 <sub>2</sub>                   | H <sub>2</sub> S | Cl | N0 <sub>2</sub> | Examples of type of environment |
|--|-------------|-----------------------------------|------------------|----|-----------------|---------------------------------|
|  |             | (proportion in 10 <sup>-9</sup> ) |                  |    |                 |                                 |
| Low                                    | (low)*      | 30                                | 7                | 7  | 50              | Ground; weather protected       |
| Moderate                               | (moderate)* | 100                               | 70               | 70 | 300             | Ground; non weather protected   |
| High                                   | (high)*     | 400                               | 400              | 70 | 500             | Naval; severe                   |

\* No figure has been published

**Table 7 – Typical conditions for each environment type according to Table 3 (mechanically and chemically active substances and climatic conditions)**

|   | Active substances concentration (classes according to Tables 5 and 6) |  |   | Relative humidity % | Mean temperature °C | Rapid changes of Temperature: qualitative estimation of temperature range |
|---|---|--|---|---------------------|---------------------|---|
|   | Mechanically active substances  | Chemically active substances             |   |                     |                     |   |
|   |   | Gaseous substances                       | Fluid substances                          |                     |                     |   |
|   | Concentration class according to Table 5                              | Concentration class according to Table 6 | Concentration class without exact figures |                     |                     |   |
| Ground; stationary; weather protected     | low   | low                                      | negligible                                | 40 to 70            | +5 to +45           | negligible  |
| Ground; stationary; non weather protected | moderate  | moderate                                 | negligible                                | 5 to 100            | -40 to +45          | low   |
| Ground; non stationary; benign            | moderate  | moderate                                 | negligible                                | 5 to 100*           | -40 to +45          | low   |
| Airborne; benign                          | low   | low                                      | negligible                                | 5 to 100            | -40 to +45          | low   |
| Airborne; moderate                        | low   | low                                      | negligible                                | 5 to 100            | -40 to +45          | low   |
| Naval; benign                             | very low  | low                                      | negligible                                | 5 to 100            | -40 to +45          | low   |
| Ground; non stationary; severe            | high  | moderate                                 | low                                       | 5 to 100            | -40 to +70          | moderate  |
| Airborne; severe                          | high  | moderate                                 | high                                      | 5 to 100            | -65 to +85          | high  |
| Naval; severe                             | moderate  | high                                     | high                                      | 10 to 100           | -40 to +70          | high  |
| Airborne; extremely severe                | high  | moderate                                 | high                                      | 5 to 100            | -65 to +85          | high  |
| Satellite; launch                         | low   | moderate                                 | low                                       | 0 to 50             | -40 to +20          | high  |
| Satellite ; Orbit                         | very low  | moderate                                 | low                                       | 0                   | -40 to +65          | moderate  |

\* 40 to 70 on board trains (railway equipment)

### 5.3 Electrical environment conditions

Reliability is also heavily dependent on electrical environment conditions (voltage and current overloads). This applies in particular to a component connected to interface circuits between an electronic circuit board and the outside environment (another equipment, especially if remotely located).

First priority is to protect the exposed components appropriately (by a system of protection comprising components designed to resist overload conditions). However, it is often found that the reliability of exposed and protected components does not match that of components located "at the heart" of an equipment. Electrical environment conditions for the active components have therefore been included (bearing in mind that the effect of residual overloads after a protection system is of concern).

The influence of the electrical environment for other families (some passive components), might equally be applied.

### 5.4 Validity model according to environment

Failures analysis undertaken on field failed active devices, during the period 1992 to 2001, have shown that:

- For the "ground; stationary; weather protected" environment, there is no package related defects, and nothing coming from the mounting process.
- For "ground; stationary; non-weather protected", "ground non-stationary; severe" and "airborne benign" environments, the main observed defects are caused by thermomechanical constraints applied to components mounted on PCBs. The failure rate related to the humidity is insignificant (for active components, especially since the generalization of the nitride based passivations). Furthermore, in these studied environments no defect related to mechanical shocks or to vibrations to chemical contamination has been observed. Consequently, these failure mechanisms have not been taken into account in the models.

Therefore, to use these models correctly, it is necessary to make appropriate qualification tests to verify these hypotheses for the considered environment. Plastic encapsulated devices are, in most of the described environments in this report, insensitive to shock and vibration.

Furthermore, for the "ground; stationary; non weather protected", it is necessary to ensure that there is no condensation on cold parts of the equipment (especially for equipment having a standby mode), and also there is no streaming on the equipment itself, this, to avoid any corrosion phenomenon.

### 5.5 Components choice

It is the responsibility of the manufacturer to guarantee the life duration specified by the final user and that components used in equipment are compatible with the environment. Therefore, premature usury phenomena shall not occur, during the useful life period of the equipment in normal utilization conditions prescribed by the final user (see 4.2.1.3).

However some components may have limited life duration, but a preventive maintenance has to be nevertheless indicated to the final user (see 4.2.1.3).

It is the responsibility of the component manufacturer to provide qualification and evaluation results of degradation mechanisms to the manufacturer and to insure that the appearance of usury mechanisms will be postponed beyond the useful life period of the equipment in normal utilization conditions, as prescribed by the final user.

Consequently, the equipment manufacturer has to choose components manufacturers who have the best "commercial practice" concerning quality, those who are ISO 9000 certified, practice the statistical process control and are under qualified manufacture line approval (or able to be).

In these conditions, there are no longer any reasons to take into consideration quality factors, and the infant mortality period related to new component technology is neglected only qualified productions lines and stabilized ones are considered here.

When an equipment manufacturer uses a new component technology, and when such a manufacturer has not been able to justify the life duration in normal use conditions of its device, the equipment manufacturer has to undertake tests allowing justification of the life duration of this component to the final user.

### 5.6 Learning during the deployment phase of new equipment

Models retained in this report allow for calculation of an electronic card to reach a reliability objective in its stabilised production phase. However, the operational reliability follow up of a newly developed electronic card, function of its deployment in the field, shows that there is a more or less long learning period, according to the improvement of the components implementation on the PCB and the components choice rectification for those having problem in the field (see Figure 1).

Each manufacturer has to calibrate the learning period according to his own experience. However experimentally, on many electronic cards and with several manufacturers, the ratio between the failure rate during the starting period of deployment and the one in the stabilized period, is between 2 and 3.

Consequently, as soon as the observed failure rate (out of non-defective removed cards: NDF) during the beginning of the deployment of an electronic card exceeds three times the estimated calculated value, a corrective action has to be taken.

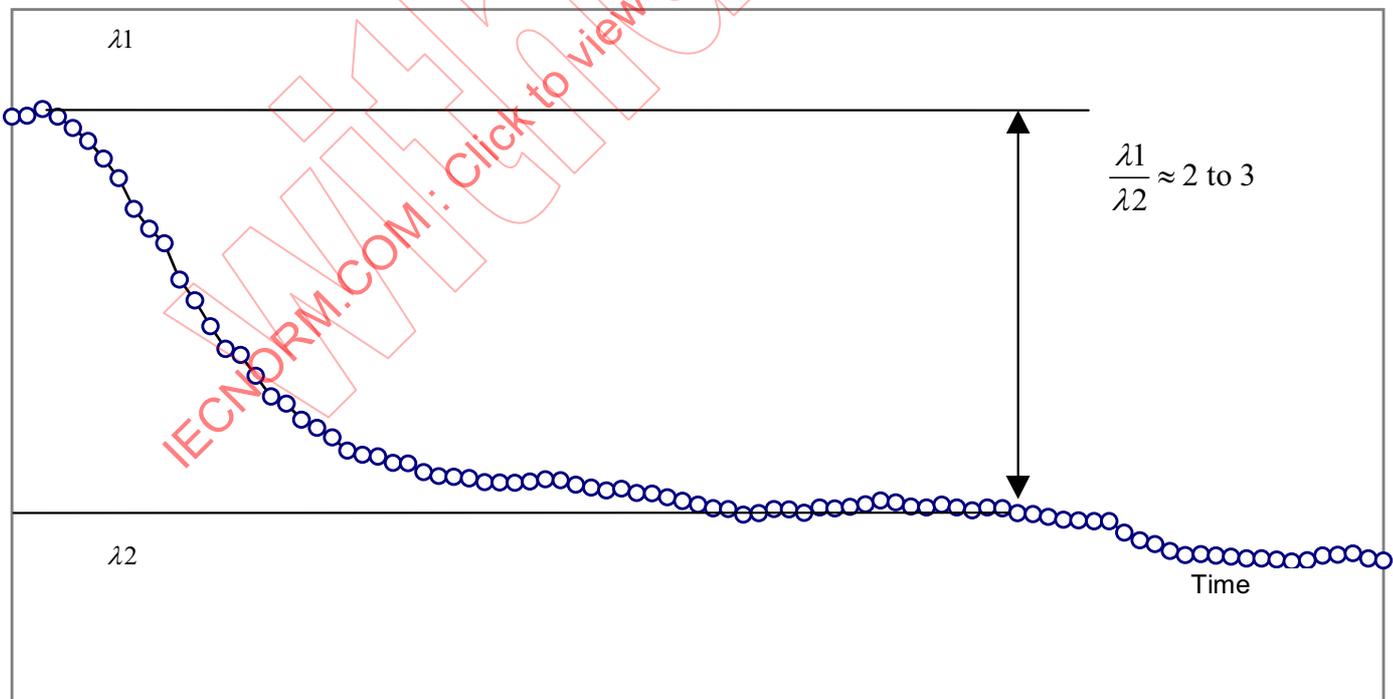


Figure 1 – Time-dependant failure rate of a new electronic printed circuit board

## 5.7 Mission profile

Estimated reliability calculation of equipment has to be done according to its field use conditions. They are defined by the mission profile.

A mission profile has to be decomposed in several homogeneous working phases, on the basis of a typical year of use. The following phases are to be considered:

- on/off working phases with various average outside temperatures seen by the equipment ;
- permanent-working phases with various average outside temperature swings seen by the equipment ;
- storage or dormant phases mode with various average outside temperature swings seen by the equipment.

For a reliability calculation, the time quantity which has to be taken into account on a field return coming from an equipment population, is therefore, the number of calendar hours of the installed population of this equipment, including working as well as storage or dormant hours.

Parameters necessary to define the mission profile of equipment are the following:

- $(t_{ae})_i$ : average outside ambient temperature surrounding the equipment, during the  $i^{\text{th}}$  phase of the mission profile.
- $(t_{ac})_i$ : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled (or the one of the component considered as the most critical for reliability, during the  $i^{\text{th}}$  phase of the mission profile).
- $\tau_i$ : annual ratio of times for the PCB, in permanent working mode with supply, and at the  $(t_{ac})_i$  temperature.
- $\tau_{on}$ : total annual ratio of time for the PCB, in permanent working mode with supply ( $\tau_{on} = \sum_{i=1}^y \tau_i$ ).
- $\tau_{off}$ : total annual ratio of time for the PCB, in non working or storage/dormant modes. ( $\tau_{on} + \tau_{off} = 1$ ).
- $n_i$ : annual number of thermal cycles seen by the components of the PCB, corresponding to the  $i^{\text{th}}$  phase of the mission profile with an average swing  $\Delta T_i$ .
- $\Delta T_i$ : average swing of the thermal variation seen by the components of the PCB, corresponding to the  $i^{\text{th}}$  phase of the mission profile.

For an on/off phase the following relation exists:  $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ae})_i$

With  $\Delta T_j$ : increase of the internal temperature of the component as compared to  $t_{ac}$ , during a  $\tau_{on}$  phase. (This is the junction temperature increase for an integrated circuit or a discrete device; this is the surface temperature increase for a passive device.) Only the third of its value has to be taken into account for a  $\Delta T_i$  calculation, taking into account the fact that thermomechanical stresses induce defects at the solder joint of the components, but also at the wire bounding of the die. The temperature to be taken into account is therefore a compromise on the internal temperature increase of the component. Some thermal simulations have shown that a third of this value is a good compromise.

$(t_{ae})_i$ : for the French climate, 11 °C is used for "Ground; stationary; non weather protected" ("ground; fixed" of MIL-HDBK-217F) environment, and 14 °C for the world-wide climate.

$(t_{ac})_i$ : is obtained, taking the mean value of the temperature increase observed on the PCB near the components as compared to the external temperature of the equipment, and adding the value of  $(t_{ae})_i$  for the considered phase.

$$t_{ac} = \text{average temperature increase of the PCB near components} + t_{ae}$$

For a storage or permanent working phase:  $\Delta T_i$  = average of the difference between maximal and minimal temperatures per cycle seen by the equipment on the considered phase. If this value is below 3 °C, the value becomes  $\Delta T_i = 0$ , taking into account the fact that for these conditions, thermomechanical stresses are thermally independent in the COFFIN-MANSON equation.

For the majority of applications, one day corresponds to one cycle, and  $\Delta T_i$  corresponds to the annual daily mean of the daylight / night temperature difference seen by the equipment park in the considered climate. For the French climate,  $\Delta T_i = 8$  °C. For the world-wide climate,  $\Delta T_i = 10$  °C.

A daily temperature variation is always superimposed on a permanent working phase according to the climatological environment of the equipment. For on/off working this daily variation is also applied on the equipment, however, only the greater temperature variation has to be taken into account, because the highest one has the main effect on the reliability of the device packages and on the mounting process.

**Table 8 – Table of climates**

| Climate type | $t_{ac}$ night | $t_{ac}$ day-light | $t_{ac}$ mean day-light/night | $\Delta T_i$ day-light/night |
|--------------|----------------|--------------------|-------------------------------|------------------------------|
| World-wide   | 5 °C           | 15 °C              | 14 °C                         | 10 °C                        |
| France       | 6 °C           | 14 °C              | 11 °C                         | 8 °C                         |

## 5.8 Mission profile examples

Mission profiles described here in after are given as examples.

### 5.8.1 Telecoms

There is only one annual working phase to consider for a permanent working.

Table 9 is given for a permanent working. Values for "ground; stationary; non weather protected"(Ground; fixed for Mil-HDBK-217F) are given for the French climate, but other climates can be calculated.

**Table 9 – Mission profiles for Telecom**

| Environment types         | Equipment types         | $(t_{ae})_i$<br>°C | $(t_{ac})_i$<br>°C | $\tau_1$ | $\tau_{on}$ | $\tau_{off}$ | $n_1$<br>cycles/year | $\Delta T_i$<br>°C/cycle |
|---------------------------|-------------------------|--------------------|--------------------|----------|-------------|--------------|----------------------|--------------------------|
| Ground; benign: ( $G_B$ ) | switching               | 20                 | 30                 | 1        | 1           | 0            | 365                  | 0                        |
| Ground; benign: ( $G_B$ ) | Transmitting            | 20                 | 40                 | 1        | 1           | 0            | 365                  | 0                        |
| Ground; fixed: ( $G_F$ )  | Transmitting and access | 11                 | 31                 | 1        | 1           | 0            | 365                  | 8                        |

### 5.8.2 Military and civilian avionics

Mission profiles described hereinafter correspond to the MIL-HDBK-217F "Airborne; Inhabited; Cargo" environment.

Several working phases are considered.

- The working rate considers only one internal working temperature for the equipment, and takes into account the total hours of annual working.

- Three phases of thermal cycling are taken in account:

. Phase 1: first daily switch on;

- . Phase 2: switch-off between two flights, while air conditioning of the plane is working;
- . Phase 3: plane on the ground, not working.

For more complex mission profiles, all the temperature's gradient seen by components during the various different working and storage cycles have to be taken into account.

**Table 10 – Mission profiles for military and civil avionics**

| Mission profile phases |                                       | Annual working rate for the equipment |                 |                  | First daily switching on      |                             | Switch-off Between two fights |                             | Ground Non-working            |                             |
|------------------------|---------------------------------------|---------------------------------------|-----------------|------------------|-------------------------------|-----------------------------|-------------------------------|-----------------------------|-------------------------------|-----------------------------|
| Plane types            | (t <sub>ac</sub> ) <sub>1</sub><br>°C | τ <sub>1</sub>                        | τ <sub>on</sub> | τ <sub>off</sub> | n <sub>1</sub><br>cycles/year | ΔT <sub>1</sub><br>°C/cycle | n <sub>2</sub><br>cycles/year | ΔT <sub>2</sub><br>°C/cycle | n <sub>3</sub><br>cycles/year | ΔT <sub>3</sub><br>°C/cycle |
| A340                   | 40                                    | 0.61                                  | 0.61            | 0.39             | 330                           | $\frac{\Delta T_j}{3} + 30$ | 330                           | $\frac{\Delta T_j}{3} + 15$ | 35                            | 10                          |
| A330                   | 40                                    | 0.54                                  | 0.54            | 0.46             | 330                           | $\frac{\Delta T_j}{3} + 30$ | 660                           | $\frac{\Delta T_j}{3} + 15$ | 35                            | 10                          |
| A320                   | 40                                    | 0.58                                  | 0.58            | 0.42             | 330                           | $\frac{\Delta T_j}{3} + 30$ | 1155                          | $\frac{\Delta T_j}{3} + 15$ | 35                            | 10                          |
| Regional plane         | 40                                    | 0.61                                  | 0.61            | 0.39             | 330                           | $\frac{\Delta T_j}{3} + 30$ | 2970                          | $\frac{\Delta T_j}{3} + 15$ | 35                            | 10                          |
| Business plane         | 40                                    | 0.22                                  | 0.22            | 0.78             | 300                           | $\frac{\Delta T_j}{3} + 30$ | 300                           | $\frac{\Delta T_j}{3} + 30$ | 65                            | 10                          |
| Weapons plane          | 60                                    | 0.05                                  | 0.05            | 0.95             | 200                           | $\frac{\Delta T_j}{3} + 50$ | 0                             | 0                           | 165                           | 10                          |
| Military cargo         | 50                                    | 0.05                                  | 0.05            | 0.95             | 250                           | $\frac{\Delta T_j}{3} + 40$ | 0                             | 0                           | 115                           | 10                          |
| Patroller              | 50                                    | 0.09                                  | 0.09            | 0.91             | 300                           | $\frac{\Delta T_j}{3} + 40$ | 0                             | 0                           | 65                            | 10                          |
| Helicopter             | 50                                    | 0.06                                  | 0.06            | 0.94             | 300                           | $\frac{\Delta T_j}{3} + 40$ | 0                             | 0                           | 65                            | 10                          |

### 5.8.3 Automotive

Mission profiles described hereinafter correspond to the MIL-HDBK-217F "Ground; mobile" environment.

Several working phases are considered..

- The working rates consider three different internal working temperatures for the equipment, and take into account the annual working hours for each of these temperatures. The overall working time is estimated to be 500 h.
- Two thermal cycling are considered:  
Phase 1: 2 night starts;  
Phase 2: 4 day light starts.
- Phase 3: non-used vehicle, dormant mode 30 days per year.

**Table 11 – Mission profiles for automotive**

| Mission profile phases | Temp. 1                               |                | Temp. 2                               |                | Temp. 3                               |                | Ratios on/off   |                  | 2 night starts                    |                             | 4 day light starts                |                             | Non used vehicle                  |                             |
|------------------------|---------------------------------------|----------------|---------------------------------------|----------------|---------------------------------------|----------------|-----------------|------------------|-----------------------------------|-----------------------------|-----------------------------------|-----------------------------|-----------------------------------|-----------------------------|
|                        | (t <sub>ac</sub> ) <sub>1</sub><br>°C | τ <sub>1</sub> | (t <sub>ac</sub> ) <sub>2</sub><br>°C | τ <sub>2</sub> | (t <sub>ac</sub> ) <sub>3</sub><br>°C | τ <sub>3</sub> | τ <sub>on</sub> | τ <sub>off</sub> | n <sub>1</sub><br>cycles/<br>year | ΔT <sub>1</sub><br>°C/cycle | n <sub>2</sub><br>cycles/<br>year | ΔT <sub>2</sub><br>°C/cycle | n <sub>3</sub><br>cycles/<br>year | ΔT <sub>3</sub><br>°C/cycle |
| Motor control          | 32                                    | 0.02<br>0      | 60                                    | 0.01<br>5      | 85                                    | 0.02<br>3      | 0.05<br>8       | 0.94<br>2        | 670                               | $\frac{\Delta T_j}{3} + 55$ | 1340                              | $\frac{\Delta T_j}{3} + 45$ | 30                                | 10                          |
| Passenger compartment  | 27                                    | 0.00<br>6      | 30                                    | 0.04<br>6      | 85                                    | 0.00<br>6      | 0.05<br>8       | 0.94<br>2        | 670                               | $\frac{\Delta T_j}{3} + 30$ | 1340                              | $\frac{\Delta T_j}{3} + 20$ | 30                                | 10                          |

## 6 Equipped printed circuit boards and hybrid circuits (IEC 60326)

### 6.1 Failure rate calculation of an equipped printed circuit board

Equipped board failure rate:  $(A+B) \times 10^{-9} / \text{hour}$ , with: A = connections and components ; B = board

$$A = \left[ \sum \lambda_s + \sum \lambda_f + \left( 1 + 3.10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times \sum \lambda_d \right]$$

Surface mounted components + Through hole components + Miscellaneous connections

$\lambda_s$  : Failure rate of each particular surface mounted component ( with its influence factors ) expressed in  $10^{-9}/\text{hour}^*$ .

$\lambda_f$  : Failure rate of each trough hole component ( with its influence factors ) expressed in  $10^{-9}/\text{hour}^*$ .

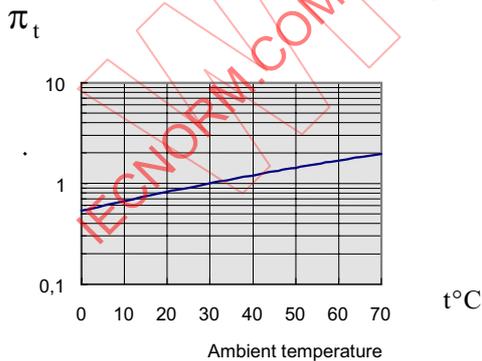
\* If the failure rate is  $3.10^{-9} / \text{h}$ , take  $\lambda_s$  (or  $\lambda_f$ ) =3

|   |                             |   |
|---|-----------------------------|---|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$ Cycles/year | $(\pi_n)_i = n_i^{0.76}$  |
|   | $n_i > 8760$ Cycles/year    | $(\pi_n)_i = 1.7 \times n_i^{0.60}$   |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |                             |   |
| For an on/off phase   |                             | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$  |
| For a permanent working phase, storage or dormant               |                             | $\Delta T_i$ =average per cycle of the $(t_{ae})$ variation, during the $i^{\text{th}}$ phase of the mission profile. |

|                                     |                    |
|-------------------------------------|--------------------|
| Miscellaneous connections           | $\lambda_d$<br>FIT |
| Manual soldering                    | 0.5                |
| Connecting with insulating transfer | 0.5                |
| Crimp...                            | 0.3                |
| Wrapped connection                  | 0.01               |
| Pressfit connection                 | 0.006              |

$(t_{ae})_i$ : average external ambient temperature of the equipment, during the  $i^{\text{th}}$  phase of the mission profile  
 $(t_{ac})_i$ : average internal ambient temperature, near the components, where the temperature gradient is cancelled.  
 $(\pi_n)_i$  :  $i^{\text{th}}$  influence factor related to the annual cycle number of thermal variation, seen by the board with an amplitude of  $\Delta T_i$ .  
 $\Delta T_i$  :  $i^{\text{th}}$  thermal variation amplitude of the mission profile.

$$B = 5.10^{-3} \cdot \pi_t \cdot \pi_c \cdot \left[ N_r \sqrt{1 + \frac{N_i}{S}} + N_p \cdot \frac{1 + 0.1\sqrt{S}}{3} \cdot \pi_L \right] \times \left( 1 + 3.10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right)$$



$N_t$  = Total number of holes (for through holes components and vias)

$S$  = Board surface ( $\text{cm}^2$ )

$N_p$  = number of tracks

Default value:

$$N_p = \frac{(\text{total number of connections})}{2} = \frac{\sum N_s + \sum N_f}{2}$$

$N_s$  : number of connections for each particular surface mounted component.

$N_f$  : number of connections for each particular through hole component.

Mathematical expression for  $\pi_t$

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_A} \right)}$$
 with  $t_A$  : ambient temperature

| Number of layers influence |                                       |
|----------------------------|---------------------------------------|
| Number of layers           | $\pi_C$                               |
| $\leq 2$                   | 1                                     |
| $> 2$                      | $0.7\sqrt{(\text{number of layers})}$ |

| Influence of the track width |      |     |      |      |      |      |
|------------------------------|------|-----|------|------|------|------|
| Predominant track width (mm) | 0.56 | 0.3 | 0.23 | 0.15 | 0.10 | 0.08 |
|                              | 5    |     |      |      |      |      |
| $\pi_L$                      | 1    | 2   | 3    | 4    | 5    | 6    |

### 6.2 Hybrid circuits

**Hybrid circuit failure rate:**  $(A + B) \times 10^{-9} / \text{hour}$   
 components

A = Add on components and packages; B = substrate and deposited components

$$A = \sum \lambda_s + \left(0.023 \times (|\alpha_s - \alpha_c|)^{1.68}\right) \times \left(2.7 \times 10^{-3} \times \left[\sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68}\right]\right) \times 0.2 \times \pi_p \times D^{1.57}$$

Add on components + package

$\lambda_s$  : Failure rate of each add on component expressed in  $10^{-9}$  /hour, (with its influence factors)\*

\* If the failure rate is  $3.10^{-9} / h$ , take  $\lambda_s = 3$

D: hybrid circuit diagonal, or distance between farrest pins, in millimeters.

|            |  |
|------------|--|
| $\alpha_s$ | Linear thermal expansion coefficient of the mounting substrate of the hybrid in ppm/°C |
| $\alpha_c$ | Linear thermal expansion coefficient of the hybrid substrate in ppm/°C                 |

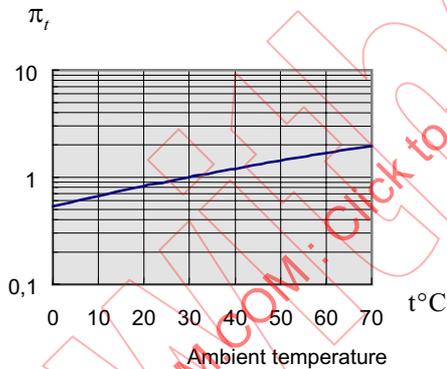
| Connecting type | $\pi_p$ |
|-----------------|---------|
| Single in line  | 1       |
| Double in line  | 2       |
| Peripheral      | 4       |

| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$    |
|---|--|-----------------------------|
|   |  | $n_i > 8760$<br>Cycles/year |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                             |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                             |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{\text{th}}$ phase of the mission profile. |                             |

$$B = \left\{ 5 \times 10^{-3} \pi_c \left[ N_i \sqrt{1 + \frac{N_i}{S}} + N_p \frac{1 + 0.1\sqrt{S}}{3} \pi_L + 0.8 N_x \right] + \pi_i \left[ \sum (0.01 R_c + 0.04 R_m) \pi_i + 0.1 C \right] \right\} \times \left( 1 + 2.7 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right)$$

interconnections, crossovers

deposited components



**Mathematical expression for  $\pi_t$**

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_A} \right)}$$

with  $t_A$  : ambient temperature

| Number of layers influence |  |
|----------------------------|--|
| Number of layers           | $\pi_C$                                |
| $\leq 2$                   | 1                                      |
| $> 2$                      | $0.7 \sqrt{\text{(number of layers)}}$ |

S = Substrate surface ( $\text{cm}^2$ )  
 $N_i$  = number of holes for interconnections

C : Number of deposited capacitors  
 $R_c$  : Number of thick film resistors having a same factor  $\pi_i$  \*  
 $R_m$  : Number of thin film resistors having a same factor  $\pi_i$  \*

| Precision factor *     | $\pi_i$ |
|------------------------|---------|
| Tolerance > 5%         | 1       |
| Tolerance from 1 to 5% | 1.5     |
| Tolerance < 1%         | 2       |

\*: Count apart resistors according to  $\pi_i$

$N_p$  = number of tracks  
 Default value:  
 $\frac{\text{(number of components connections)}}{2}$

$N_x$  : number of crossover

| Tracks width influence |      |      |      |      |      |      |
|------------------------|------|------|------|------|------|------|
| Predominant width (mm) | 0,56 | 0,35 | 0,23 | 0,15 | 0,10 | 0,08 |
| $\pi_L$                | 1    | 2    | 3    | 4    | 5    | 6    |

## 7 Integrated circuits

### 7.1 Validity domain

The end of life period of an integrated circuit is supposed to appear far beyond the utilization period of the equipment. This assumption has to be assessed by a preliminary qualification.

The main failure mechanisms to assess are following:

- For silicon technologies:
  - electromigration;
  - oxides ageing;
  - hot electrons;
  - charge gain and charge (for the write – erase cycles of the various programmable memories).
- For GaAs technologies:
  - gate sink;
  - Ohmic contact degradation;
  - gate and drain lagging;
  - electromigration.
- Packages:
  - thermal fatigue;
  - purple plague.

Estimated failure rates are valid, only if the coldest part temperature of the considered card is over the dew point temperature.

The model does not include the failure rate due to soft errors<sup>1</sup> provoked by the creation of electron-hole pair, on the passage of alpha particle emitted by the package materials. This failure rate due to soft errors may be of the same order of magnitude as the intrinsic failure rate, especially for dynamic memories.

For interface circuits, the models include a failure rate considered to be constant, due to external electrical influences. This failure rate depends on the electrical environment of the equipment, given that the equipment does have primary or secondary protections, depending on the state of the art of the period observed. (For the purposes of this report, interface circuits are taken to be circuits or devices connecting the equipment to the outside environment.)

### 7.2 Junction temperature evaluation of an integrated circuit

By default, the following simplified method will be used:

#### 7.2.1 The junction temperature is given according to the average power dissipated in the integrated circuit by one of the following equations:

$$\begin{aligned} t_j &= t_a + P \times R_{ja} \\ t_j &= t_c + P \times R_{jc} \end{aligned}$$

in which

- $t_a$  is the ambient temperature around the integrated circuit (°C);
- $t_c$  is the case temperature of the integrated circuit (°C);
- $t_j$  is the junction temperature of the integrated circuit (°C);
- $R_{ja}$  is the junction-ambient thermal resistance of the integrated circuit (°C/W);
- $R_{jc}$  is the junction-case thermal resistance of the integrated circuit (°C/W);
- $P$  is the average power dissipated by the integrated circuit (Watt).

<sup>1</sup> When the function is fully retrievable without outside intervention.

NOTE The following equation applies:

$$\text{Junction-ambient thermal resistance} = \text{junction-case thermal resistance} + \text{case-ambient thermal resistance}$$

## 7.2.2 Evaluating thermal resistance

### 7.2.2.1 Preferred method

The preferred method is to take the thermal resistance value specified or published by the manufacturers.

### 7.2.2.2 Default method

By default, the values given in table 12 will be taken according to S and K, where:

S: is the number of pins of the package.

K: is the cooling factor given, according to the velocity of air V in m/s, by the following equation:

$$K = \frac{0.59V + 1.11}{V + 0.7}$$

Practical values of K are given in Table 13.

**Table 12 – Thermal resistance as a function of package type, the pin number and airflow factor**

| <b>Package thermal resistance of integrated circuits</b><br>as a function of:<br>S: number of pins<br>K: airflow factor ( <i>see table 13</i> ) |  |   |
|---|--|---|
|   | Junction-case<br>thermal resistance<br>$R_{jc}$ (°C/W) | Junction-ambient<br>thermal resistance<br>$R_{ja}$ (°C/W)       |
| DIL ceramic package   | $0.23 \left( 10 + \frac{1520}{S+3} \right)$            | $(0.23 + 0.66K) \left( 10 + \frac{1520}{S+3} \right)$           |
| DIL plastic package   | $0.33 \left( 10 + \frac{1520}{S+3} \right)$            | $(0.23 + 0.66K) \left( 10 + \frac{1520}{S+3} \right)$           |
| PLCC plastic package  | $0.28 \left( 15 + \frac{1600}{S+3} \right)$            | $(0.28 + 0.72K) \left( 10 + \frac{1600}{S+3} \right)$           |
| SOJ and SOL plastic package   | $0.28 \left( 15 + \frac{1760}{S+3} \right)$            | $(0.28 + 0.72K) \left( 10 + \frac{1760}{S+3} \right)$           |
| TSOP plastic package  | $0.4 \left( 20 + \frac{2500}{S+3} \right)$             | $(0.4 + 0.6K) \left( 20 + \frac{2500}{S+3} \right)$             |
| PGA ceramic package   | $0.33 \left( 10 + \frac{1440}{S+3} \right)$            | $(0.33 + 0.66K) \left( 10 + \frac{1440}{S+3} \right)$           |
| QFP plastic package   | $0.4 \left( 27 + \frac{2260}{S+3} \right)$             | $(0.4 + 0.6K) \left( 27 + \frac{2260}{S+3} \right)$             |
| BGA plastic package   | $0.4 \left( 6.6 + \frac{1.1 \times 10^6}{S^2} \right)$ | $(0.4 + 0.6K) \left( 6.6 + \frac{1.1 \times 10^6}{S^2} \right)$ |

**Table 13 – Typical values of the air flow speed V, and the air flow factor K**

|                           | V (m/s) | K   |
|---------------------------|---------|-----|
| Natural convection        | 0.15    | 1.4 |
| Slightly assisted cooling | 0.5     | 1.2 |
| Fan assisted cooling      | 1       | 1   |
| Forced cooling            | 4       | 0.7 |

### 7.2.2.3 Evaluating the average power dissipated by an integrated circuit P (Watt)

Preferably use the real average power dissipated by the integrated circuit. By default, use the following method:

#### 7.2.2.3.1 CMOS family

##### 7.2.2.3.1.1 CMOS digital circuit, other than memory and 74 ACT family circuits

Calculate:

$$P = \frac{P_1(P_1 + 3.5)}{3P_1 + 5}$$

The value of  $P_1$  is calculated from one or the other following formulas:

a) If an equivalent capacitance  $C_{pd}$  is specified :

$$P_1 = (V_{cc}^2 \times f) \times [C_{pd} (\text{number of individual functions } *) + C_L (\text{number of output pin})] \times 10^{-6}$$

NOTE 2

b) If a current consumption  $I_S$  is specified at a specified frequency  $f_S$  ( MHz):

$$P_1 = V_{cc} I_S \frac{f}{f_S} + V_{cc}^2 f C_L (\text{number of outputs}) \times 10^{-6}$$

where

$P_1$  is the maximum power (W);

$V_{cc}$  is the supply voltage (V);

$f$  is the working frequency (MHz);

$C_{pd}$  is the equivalent capacitance for calculating dissipated power for each individual function, (pF);

$C_L$  is the load capacitance on outputs, for each output, (pF);

$I_S$  is the specified value of the consumption current at a specified frequency  $f_S$ , and when outputs are not charged;

$f_S$  is the value of the specified frequency for the consumption (MHz).

NOTE 1 - In case b, the number of individual functions has disappeared, because the consumption current is only specified for circuits with one complex elementary function.

NOTE 2 - Sometimes the working frequency  $f$  is assimilated to  $f_S$ .

The default values for  $V_{cc}$ ,  $C_L$ ,  $C_{pd}$ ,  $f$ , are as follows:

$V_{cc}$  is the 5 V or 3 V

$C_L$  is the 50 pF

$f$  is the 30 MHz for HC family; 50 MHz for AC family.

$C_{pd}$  according to specification or catalogue.

### 7.2.2.3.1.2 CMOS digital circuits of the 74 ACT family

Calculate:

$$P = \frac{P_1(P_1 + 3.5)}{3P_1 + 5}$$

with

$$P_1 = 1,6 \cdot 10^{-3} \times V_{cc} \times (\text{number of input pins}) + V_{cc}^2 \times f \times 10^{-6} [C_{pd} \times (\text{number of individual functions}^*) + C_L \times (\text{number of output pins})]$$

The default values for  $V_{cc}$ ,  $C_L$ ,  $C_{pd}$ ,  $f$ , are as follows:

$V_{cc}$  is the 5 V;

$C_L$  is the 50 pF;

$C_{pd}$  according to specification or catalogue;

$f$  is the 50 MHz.

### 7.2.2.3.1.3 Bipolar, gallium arsenide, NMOS digital circuits

Calculate:

$$P = \frac{P_M(P_M + 3.5)}{3P_M + 5} \text{ (in Watts)}$$

where  $P_M$  = maximum continuous power =  $V_{cc}$  typical  $\times$   $I_{cc}$  maximum

### 7.2.2.3.1.4 Circuits with a standby mode (for example: MOS memories)

Calculate:

$$P = P_p \frac{d}{100} + P_r \times \left(1 - \frac{d}{100}\right)$$

in which

$d$  is the activation ratio as a percentage;

$P_p$  is the worst case power consumption (specified or published);

$P_r$  is the power consumed in standby mode:  $P_r = (V_{cc} \text{ typical}) \times (I_{cc} \text{ stand by})$ .

## 7.3 The reliability model

### 7.3.1 General form of the model and definitions

- For an active device, the failure rate is noted  $\lambda$  and breaks down as :

$$\lambda = \lambda_{die} + \lambda_{package}$$

in which

$$\lambda_{die} = \lambda_{thermal \ effects} + \lambda_{EOS \ effects}$$

and

$$\lambda_{package} = \lambda_{thermomechanical \ effects}$$

**MATHEMATICAL MODEL :**

$$\lambda = \left\{ \underbrace{\lambda_1 \times N \times e^{-0.35 \times a} + \lambda_2}_{\lambda_{die}} \times \left\{ \frac{\sum_{i=1}^y (\pi_i)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\} + \underbrace{2.75 \times 10^{-3} \times \pi_\alpha \times \left( \sum_{i=1}^z (\pi_n)_i \times (\Delta T_i)^{0.68} \right)}_{\lambda_{package}} \times \lambda_3 + \underbrace{\left\{ \frac{\pi_I \times \lambda_{EOS}}{\lambda_{overstress}} \right\}}_{\lambda_{overstress}} \right\} \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $\lambda_1$  : per transistor base failure rate of the integrated circuit family. See Table 16.
- $\lambda_2$  : failure rate related to the technology mastering of the integrated circuit. See Table 16.
- $N$  : number of transistors of the integrated circuit.
- $a$  : [(year of manufacturing) - 1998].
- $(\pi_i)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the integrated circuit mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the integrated circuit for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the integrated circuit. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the integrated circuit being in storage (or dormant). With  $\tau_{on} + \tau_{off} = 1$
- $\pi_\alpha$  : influence factor related to the thermal expansion coefficients difference, between the mounting substrate and the package material.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- $\lambda_3$  : base failure rate of the integrated circuit package. See Table 17a and 17b
- $\pi_I$  : influence factor related to the use of the integrated circuit (interface or not).
- $\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application..

| Technological structure          | Temperature factor $\pi_t$  |
|----------------------------------|---|
| MOS<br>BiCMOS (low voltage)      | $e^{\left[ A \left( \frac{1}{328} - \frac{1}{273+t_j} \right) \right]}$<br>A=3480 ; (Ea=0.3 eV) |
| Bipolar<br>BiCMOS (high voltage) | $e^{\left[ A \left( \frac{1}{328} - \frac{1}{273+t_j} \right) \right]}$<br>A=4640 ; (Ea=0.4 eV) |
| AsGa Numerical                   | $e^{\left[ A \left( \frac{1}{373} - \frac{1}{273+t_j} \right) \right]}$<br>A=3480 ; (Ea=0.3 eV) |
| AsGa MMIC                        | $e^{\left[ A \left( \frac{1}{373} - \frac{1}{273+t_j} \right) \right]}$<br>A=4640 ; (Ea=0.4 eV) |

$t_j$  = Junction temperature in °C .

|  |   |
|--|---|
| Mathematical expression of the influence factor $\pi_\alpha$                 | $\pi_\alpha = 0.06 \times (\alpha_S - \alpha_C)^{1.68}$ |
| Mismatch between substrate and package for the thermal expansion coefficient | $ \alpha_S - \alpha_C $                                 |
| $\alpha_S$   | See Table 14  |
| $\alpha_C$   | See Table 14  |

| Interface circuits<br>Typical calculated values |  | $\lambda_{EOS}$<br>FIT                 | $\pi_I$ |   |
|---|--|--|---------|---|
| Function  | Electrical environment                   |  |         |   |
| Interfaces                                      | Computer                                 | 10                                     | 1       |   |
|   | Telecoms                                 | switching                              | 15      | 1 |
|   |  | transmitting, access, subscriber cards | 40      | 1 |
|   |  | subscriber equipment                   | 70      | 1 |
|   | Railways, payphone                       | 100                                    | 1       |   |
|   | Civilian avionics (on board calculators) | 20                                     | 1       |   |
| Non Interfaces                                  | Voltage supply, Converters               | 40                                     | 1       |   |
|   | All electrical environment               | -                                      | 0       |   |

|   |   |                                     |
|---|---|-------------------------------------|
| Mathematical expression of the                                  | $n_i \leq 8760$<br>Cycles/year  | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$                                    | $n_i > 8760$<br>Cycles/year   | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |   |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ae})_i$                                    |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile. |                                     |

**Table 14 – Thermal expansion coefficients  $\alpha_S$  and  $\alpha_C$ .**

| Linear thermal expansion coefficients | Material type                         | Values in ppm/°C |
|---------------------------------------|---------------------------------------|------------------|
| $\alpha_S$ (Substrate)                | Epoxy Glass (FR4, G-10)               | 16               |
|                                       | PTFE Glass (polytetrafluoroethylene)  | 20               |
|                                       | Flexible substrate (Polyimide Aramid) | 6.5              |
|                                       | Cu/Invar/Cu (20/60/20)                | 5.4              |
| $\alpha_C$ (Component)                | Epoxy (Plastic package)               | 21.5             |
|                                       | Alumina (ceramic package)             | 6.5              |
|                                       | Kovar (Metallic package)              | 5                |

**Table 15 – Failure distribution (for non interfaces integrated circuits)**

| Environment type                | Stuck at Valim in % | Stuck at ground % | Open circuit % |
|---------------------------------|---------------------|-------------------|----------------|
| Ground; Benign                  | 50                  | 50                | 0              |
| Ground; Fixed<br>Ground; mobile | 5                   | 5                 | 90             |

- For interface circuits, quasi totalities of defects are open circuits.

**Calculation example:**

A microprocessor failure rate has to be calculated for an "automotive passenger compartment" mission profile. This microprocessor has the following characteristics:

- Manufacturing year : 1999 a=1999-1998=1 (See necessary information section)
- Technology : numerical CMOS  $\lambda_1=3.4 \times 10^{-6}$  and  $\lambda_2=1.7$  ( See Table 16)
- Transistor number :  $1.5 \times 10^6$
- Dissipated power by the component : 0.5 W
- PQFP 80 pins package  $\alpha_C=21.5$  (See Table 14)
- Mounting substrate FR4  $\alpha_S=16$  (See Table 14) Then  $\pi_\alpha=1$

This circuit is not an interface. Then  $\pi_I=0$ .

Temperature increase related to fact that the circuit works, is given with natural convection (then K=1.4) by the following formulas. Junction – ambient thermal resistance for the PQFP package is given in table 12 :

$$RTH_{ja} = (0.4 + 0.6 \times 1.4) \times \left( 27 + \frac{2260}{80 + 3} \right) = 67^\circ C/W \quad \text{Then } \Delta T_j = 67 \times 0.5 = 34^\circ C$$

Mission profile from table 6 is following :

$$\begin{aligned} (t_j)_1 = 27 + 34 = 61^\circ C & \quad \text{then} & \quad (\pi_t)_1 = e^{\left[ 3480 \left( \frac{1}{328} - \frac{1}{273 + 61} \right) \right]} = 1.21 \\ (t_j)_2 = 30 + 34 = 64^\circ C & \quad \text{then} & \quad (\pi_t)_2 = e^{\left[ 3480 \left( \frac{1}{328} - \frac{1}{273 + 64} \right) \right]} = 1.33 \\ (t_j)_3 = 85 + 34 = 118^\circ C & \quad \text{then} & \quad (\pi_t)_3 = e^{\left[ 3480 \left( \frac{1}{328} - \frac{1}{273 + 118} \right) \right]} = 5.5 \end{aligned}$$

$(t_{ae})_1$  is  $14^\circ C$  for world wide climate

$$(t_{ae})_1 \text{ average temperature during the working phases is : } \frac{0.006 \times 27 + 0.046 \times 30 + 0.006 \times 85}{0.058} = 35^\circ C$$

For the night starts phase,  $t_{ae}$  is  $5^\circ C$  ; for the day light starts phase  $t_{ae}$  is  $15^\circ C$ , then :

$$\Delta T_1 = \left( \frac{34}{3} + 35 \right) - 5 = 41 \quad \Delta T_2 = \left( \frac{34}{3} + 35 \right) - 15 = 31 \quad \Delta T_3 = 10$$

$$\lambda = \left\{ \underbrace{\left[ 3.4 \times 10^{-6} \times 1.5 \times 10^6 \times e^{-0.35 \times 1} + 3.4 \right]}_{\lambda_{die}} \times \left\{ \frac{1.21 \times 0.006 + 1.33 \times 0.046 + 5.5 \times 0.006}{0.058 + 0.942} \right\} + \left[ 2.75 \times 10^{-3} \times \left( (670)^{0.76} \times (41)^{0.68} + (1340)^{0.76} \times (31)^{0.68} + (30)^{0.76} \times (10)^{0.68} \right) \times 10.2 \right] + \left\{ \frac{0 \times \lambda_{EOS}}{\lambda_{overstress}} \right\} \right\} \times 10^{-9} / h$$

The failure rate for this component will be 126 FIT for this mission profile.

**Table 16 – Values of  $\lambda_1$  and  $\lambda_2$  for integrated circuits families**

| ABBREVIATIONS   | TYPES  | N<br>Is the<br>representative<br>number of<br>transistors | $\lambda_1$<br>in<br>FIT | $\lambda_2$<br>in<br>FIT |
|---|--|---|--------------------------|--------------------------|
| <b>Silicon: MOS : Standard circuits (3)</b>   |  |   |                          |                          |
| ROM<br>DRAM/VideoRAM/AudioRAM<br>High speed SRAM, FIFO<br>Low consumption SRAM<br>Double access SRAM<br>EPROM,UVPROM,REPROM<br>OTP<br>FLASH<br>EEPROM, flash EEPROM | Digital circuits, Micros, DSP  | 4 per gate  | $3.4 \cdot 10^{-6}$      | 1.7                      |
|   | Linear circuits  | Actual number   | $1.0 \cdot 10^{-2}$      | 4.2                      |
|   | Digital / linear circuits (Telecom, CAN, CNA, RAMDAC, ...)                                     | Actual number   | $2.7 \cdot 10^{-4}$      | 20                       |
|   | MEMORIES:<br>Read only memory  | 1 per bit   | $1.7 \cdot 10^{-7}$      | 8.8                      |
|   | Dynamic, Read Access Memory  | 1 per bit   | $1.0 \cdot 10^{-7}$      | 5.6                      |
|   | Static Read Access Memory - First in First out register; ("mixed MOS ")                        | 4 per bit   | $1.7 \cdot 10^{-7}$      | 8.8                      |
|   | Static Read Access Memory - Low consumption; (CMOS)  | 6 per bit   | $1.7 \cdot 10^{-7}$      | 8.8                      |
|   | Double Access Static RAM   | 8 per bit   | $1.7 \cdot 10^{-7}$      | 8.8                      |
|   | Electrically programmable, UV erasable - Read only memory                                      | 1 /programmable point }<br>2 /programmable point }        | $2.6 \cdot 10^{-7}$      | 34                       |
|   | One time programmable EPROM  |   |                          |                          |
|   | Electrically programmable and erasable (block) (1)   |   | $6.5 \cdot 10^{-7}$      | 16                       |
| Electrically programmable and erasable (word) (2)   |  |   |                          |                          |
| (1) Whole memory array or blocks of words erasable (2) Blocks of words or word erasable (3) MOS include CMOS, HCMOS, NMOS, ... technologies                         |  |   |                          |                          |
| <b>Silicon: MOS : Asic circuits</b>   |  |   |                          |                          |
| LCA (RAM based)<br>PLD (GAL, PAL) (2)<br>CPLD (EPLD,MAX,FLEX, FPGA, etc)  | Standard Cell, Full Custom   | 4 per gate  | $1.2 \cdot 10^{-3}$      | 10                       |
|   | Gate Arrays  | 4 per gate  | $2.0 \cdot 10^{-5}$      | 10                       |
|   | USER PROGRAMMABLE LOGIC DEVICE:<br>Logic Cell Array electrically configured by external memory | 40 per gate (1)   | $4.0 \cdot 10^{-5}$      | 8.8                      |
|   | Electrically Programmable and erasable (AND/OR array)  | 3 par grid point  | $1.2 \cdot 10^{-3}$      | 16                       |
|   | Electrically Programmable (interconnected macrocells array) (2)                                | 100 per macrocell   | $2.0 \cdot 10^{-5}$      | 34                       |
| (1) or 4000 per macrocell ; (2) EEPROM, EPROM, or Antifuse technologies.  |  |   |                          |                          |
| <b>Silicon: Bipolar circuits (1)</b>  |  |   |                          |                          |
| SRAM<br>PROM,<br>PLD (PAL)  | Digital circuits   | 3 per gate  | $6.0 \cdot 10^{-4}$      | 1.7                      |
|   | Linear circuits (FET, others)  | Actual number   | $2.2 \cdot 10^{-2}$      | 3.3                      |
|   | MMIC   | Actual number   | 1.0                      | 3.3                      |
|   | Linear / Digital circuits, low voltage (<30V)  | Actual number   | $2.7 \cdot 10^{-3}$      | 20                       |
|   | Linear / Digital circuits, high voltage (>=30V)  | Actual number   | $2.7 \cdot 10^{-2}$      | 20                       |
|   | MEMORIES – PROGRAMMABLE ARRAYS- GATE ARRAYS:<br>Static read access memories                    | 2.5 per bit   | $3.0 \cdot 10^{-4}$      | 1.7                      |
|   | Programmable read only memory  | 1.2 /, programmable point                                 | $1.5 \cdot 10^{-4}$      | 32                       |
|   | One time electrically programmable logic array (AND / OR arrays)                               | 1.6 per grid point  | $1.5 \cdot 10^{-4}$      | 32                       |
|   | Gate arrays  | 3 per gate  | $1.0 \cdot 10^{-3}$      | 10                       |
|   | Bipolar include : TTL, MTTL, LSTTL, FET, JFET, ECL, etc... technologies.                       |   |                          |                          |
| <b>Silicon: Bipolar and MOS circuits ( BICMOS)</b>  |  |   |                          |                          |
| SRAM  | Digital circuits   | 4 per gate  | $1.0 \cdot 10^{-6}$      | 1.7                      |
|   | Linear / digital circuits low voltage (< 6V)   | Actual number   | $2.7 \cdot 10^{-4}$      | 20                       |
|   | Linear / digital circuits, high voltage (>= 6V) and Smart Power                                | Actual number   | $2.7 \cdot 10^{-3}$      | 20                       |
|   | Static Read Access Memory  | 4 per bit   | $6.8 \cdot 10^{-7}$      | 8.8                      |
|   | Gate arrays  | 4 per gate  | $6.4 \cdot 10^{-5}$      | 10                       |
| <b>Gallium arsenide</b>   |  |   |                          |                          |
| Digital   | with only normally on transistors.   | 5 per gate  | 2.5                      | 25                       |
| Digital   | with normally off and normally on transistors.   | 3 per gate  | $4.5 \cdot 10^{-4}$      | 16                       |
| MMIC  | Low noise or low power (< 100mW) microwave circuits.   | Actual number   | 2.0                      | 20                       |
| MMIC  | Power (> 100mW) microwave circuits.  | Actual number   | 4.0                      | 40                       |

**METHOD-1:**

**Table 17a –  $\lambda_3$  values for integrated circuits as a function of S  
(pin number of the package)**

| Abbreviation           | Material type | Description  | Pin number: S           | $\lambda_3$ in FIT        |      |
|------------------------|---------------|--|-------------------------|---------------------------|------|
| SO ,SOP:1.27 mm pitch  | Epoxy         | Plastic Small Outline, L lead; Widths: 3.8 – 7.5 mm                      | 4 to 40                 | $= 0.012 \times S^{1.65}$ |      |
| Power SO               | Epoxy         | idem SO with heat sink   |                         | idem SO                   |      |
| SOJ: 1.27 mm pitch     | Epoxy         | Plastic Small Outline, J Lead; Width: 10.16 mm                           | 28 to 44                | $= 0.023 \times S^{1.5}$  |      |
| VSOP: 0.76 mm pitch    | Epoxy         | Very Small Outline, L Lead; Width: 10.16 mm                              | 40 to 56                | $= 0.011 \times S^{1.47}$ |      |
| SSOP: 0.65 mm pitch    | Epoxy         | Shrink Small Outline, L Lead; Width: 10.16 mm                            | 8 to 56                 | $= 0.013 \times S^{1.35}$ |      |
| TSSOP: 0.65 mm pitch   | Epoxy         | Thin Shrink Small Outline, L Lead; Widths: 4.1 - 6.1 mm                  | 8 to 38                 | $= 0.011 \times S^{1.4}$  |      |
| TSOP I: 0.55 mm pitch  | Epoxy         | Thin Small Outline, L Lead on small edge; Length: 11.8 mm                | 18 to 32                | $= 0.54 \times S^{0.4}$   |      |
| TSOP I: 0.5 mm pitch   | Epoxy         | Thin Small Outline, L Lead on small edge; Length: 18.4 mm                | 18 to 32                | $= 1.0 \times S^{0.36}$   |      |
| TSOP II: 0.8 mm pitch  | Epoxy         | Thin Small Outline, L Lead on long edge; Width: 10.16mm.                 | 28 to 54                | $= 0.04 \times S^{1.2}$   |      |
| TSOP II: 0,65 mm pitch | Epoxy         | Thin Small Outline, L Lead on long edge; Width: 10.16mm.                 | 34 to 60                | $= 0.042 \times S^{1.1}$  |      |
| TSOP II: 0,5 mm pitch  | Epoxy         | Thin Small Outline, L Lead on long edge; Width: 10.16mm                  | 34 to 60                | $= 0.075 \times S^{0.9}$  |      |
| TSOP II: 0,4 mm pitch  | Epoxy         | Thin Small Outline, L Lead on long edge; Width: 10.16mm                  | 34 to 60                | $= 0.13 \times S^{0.7}$   |      |
| PLCC: 1,27 mm pitch    | Epoxy         | Plastic Leaded Chip Carrier, J Lead, all bodies                          | 20 to 84                | $= 0.021 \times S^{1.57}$ |      |
| CLCC: 1,27 mm pitch    | Alumina       | Ceramic Leadless (and Leaded) Chip Carrier, all bodies                   |                         | idem PLCC                 |      |
| MQUAD: 1,27 mm pitch   | Kovar         | Metallic Quad Flat Package (PLCC footprint); all bodies                  |                         | idem PLCC                 |      |
| PQFP, TQFP             | Epoxy         | Plastic (Thin) Quad Flatpack, L Lead, Bodies defined in following column | 5x5 mm <sup>2</sup>     | 32 to 40                  | 1.3  |
|                        |               |  | 10x10 mm <sup>2</sup>   | 40 to 60                  | 4.1  |
|                        |               |  | 14x14 mm <sup>2</sup>   | 60 to 68                  | 7.2  |
|                        |               |  | 14x20 mm <sup>2</sup>   | 68 to 110                 | 10.2 |
|                        |               |  | 28x28 mm <sup>2</sup>   | 110 to 225                | 23   |
|                        |               |  | 32x32 mm <sup>2</sup>   | 225 to 280                | 29   |
|                        |               | 40x40 mm <sup>2</sup>  | 280 to 304              | 42                        |      |
| ED QUAD, Power QUAD    | Epoxy         | idem PQFP with heat sink (exposed slug)                                  |                         | idem PQFP                 |      |
| CQFP, CERQUAD          | Alumina       | Ceramic Quad Flat pack   |                         | idem PQFP                 |      |
| MQFP, MQUAD            | Kovar         | Metallic Quad Flat pack  |                         | idem PQFP                 |      |
| PBGA                   | Epoxy         | Plastic Ball Grid Array- pas >1mm. Bodies defined in following column    | 13.5x15 mm <sup>2</sup> | 64 to 80                  | 11.4 |
|                        |               |  | 17.4x19 mm <sup>2</sup> | 80 to 160                 | 16.6 |
|                        |               |  | 23x23 mm <sup>2</sup>   | 160 to 280                | 26.6 |
|                        |               |  | 35x35 mm <sup>2</sup>   | 280 to 400                | 51.3 |
| SBGA                   | Epoxy         | Shrink BGA-pas 1mm-Corps 42.5x42.5 mm <sup>2</sup>                       | 580                     | 71                        |      |
| SBGA                   | Epoxy         | Shrink BGA-pas 1mm-Corps 27x27 mm <sup>2</sup>                           | 672                     | 33                        |      |
| CBGA                   | Alumina       | Ceramic  |                         | idem PBGA                 |      |
| PDIL                   | Epoxy         | Plastic Dual In Line   | 8 to 64                 | $= 9 + 0.09 \times S$     |      |
| CDIL, CERDIP           | Alumina       | Ceramic Dual In Line   | 8 to 64                 | $= 9 + 0.09 \times S$     |      |
| PPGA                   | Epoxy         | Plastic Pin Grid Array   | 40 to 160               | $= 9 + 0.09 \times S$     |      |
| CPGA                   | Alumina       | Ceramic Pin Grid Array   | 40 to 160               | $= 9 + 0.09 \times S$     |      |

**METHOD-2:****Table 17b –  $\lambda_3$  values for surface mounted integrated circuits packages as a function of D (package diagonal)**

| Packages types  | Examples   | $\lambda_3$ in FIT            |
|---|--|-------------------------------|
| Two rows connections packages   | SO; SOP; SOJ; VSOP; SSOP; TSSOP; TSOP I; TSOP II; etc... | $= 0.024 \times D^{1.68}$ (1) |
| Peripheral connections packages   | PLCC; CLCC; MQAD; PQFP; TQFP; CQFP; MQFP; etc...         | $= 0.048 \times D^{1.68}$ (2) |
| Matrix connections packages   | PBGA; CBGA; SBGA; $\mu$ BGA; CSP; etc...                 | $= 0.073 \times D^{1.68}$ (3) |
| Bare die with epoxy drop  | COB (chip on board)                                      | $= 0.048 \times D^{1.68}$ (4) |
| <p>Note (1) : <math>D = \left[ \left( \left( \frac{S}{2} - 1 \right) \times (pitch) \right)^2 + (Width)^2 \right]^{\frac{1}{2}}</math></p> <p>Note (2) : <math>D = \left[ \left( \left( \frac{S}{4} - 1 \right) \times (pitch) \right)^2 + (Width)^2 \right]^{\frac{1}{2}}</math></p> <p>Note (3) : <math>D = \left[ (Length)^2 + (Width)^2 \right]^{\frac{1}{2}}</math></p> <p>Note (4) : D report area diagonal</p> |  |                               |

IECNORM.COM: Click to view the full PDF of IEC TR 62380:2004

## 8 Diodes and thyristors, transistors, optocouplers (IEC 60747-xx)

### 8.1 Evaluating the junction temperature of diodes and transistors

To evaluate the junction temperature of a transistor or diode, the preferred method for critical cases is to measure or calculate on the basis of thermal resistive network models. By default, the following simplified method will be used:

The junction temperature is given according to the average dissipated power, by one of the following equations:

|   |
|---|
| $t_j = t_a + P \times R_{ja}$ $t_j = t_c + P \times R_{jc}$ |
|---|

where:

$t_a$  is the ambient temperature around the case (°C);

$t_c$  is the case temperature (or socket temperature) (°C);

$t_j$  is the junction temperature (°C);

$R_{ja}$  is the Thermal resistance (junction-ambient) of the component (°C/W);

$R_{jc}$  is the Thermal resistance junction-case or mounting base) (°C/W);

$P$  is the average power dissipated (Watt).

Table 18 gives various thermal resistance values.

The first column gives the junction-case thermal resistance  $R_{jc}$  for power components or certain applications (such as use of a heat sink or insertion in a socket).

The second column gives the junction-ambient thermal resistance  $R_{ja}$  for components used in conditions of natural cooling, without additional heat sink.

The third column gives the junction-ambient thermal resistance for components soldered in a "surface mount" production line.

Thermal resistance depends largely on the type of case, but also on the size of the die and the internal fixing mode (bonding, hard solder, soft solder): the values given represent realistic examples.

Note the following equation:

|   |
|---|
| $\text{(junction - ambient) thermal resistance} = \text{(junction - case) thermal resistance} + \text{(case - ambient) thermal resistance}$ |
|---|

**Table 18 – Values of  $\lambda_B$  and junction resistances  
for active discrete components**

| Package abbreviations      | R <sub>jc</sub> | R <sub>ja</sub> | R <sub>ja</sub> mounted<br>component | $\lambda_B$ |
|----------------------------|-----------------|-----------------|--------------------------------------|-------------|
|                            | °C/W            | °C/W            | °C/W                                 | FIT         |
| TO-18                      | 130             | 450             |                                      | 1           |
| TO-39                      | 35              | 200             |                                      | 2.0         |
| TO-92                      | 100             | 300             |                                      | 1           |
| SOT-23                     |                 |                 | 400                                  | 1.0         |
| SOT-143                    |                 |                 | 400                                  | 1.0         |
| SOT-223                    |                 |                 | 85                                   | 3.4         |
| SOT-323                    |                 |                 | 600                                  | 0.8         |
| SOT-343                    |                 |                 | 600                                  | 0.8         |
| SOT-346                    |                 |                 | 500                                  | 1           |
| SOT-363                    |                 |                 | 600                                  | 0.8         |
| SOT-457                    |                 |                 | 350                                  | 1           |
| SOT-89                     |                 |                 | 125                                  | 2.0         |
| SOT-32 (TO-126)            | 10              | 100             |                                      | 5.3         |
| SOT-82                     | 10              | 100             |                                      | 5.3         |
| DPACK (SOT428)             |                 |                 | 30                                   | 5.1         |
| D2PACK                     |                 |                 | 15                                   | 5.7         |
| TO-220                     | 3               |                 |                                      | 5.7         |
| TO-218 (SOT-93)            | 1.5             |                 |                                      | 6.9         |
| TO-247                     | 1               |                 |                                      | 6.9         |
| ISOTOP                     | 0.25            |                 |                                      | 20.0        |
| SOT-90B (optocoupler)      |                 | 250             |                                      | 4.1         |
| SO-8 (optocoupler)         |                 |                 | 300                                  | 4.5         |
| DO-34 (DO-204AG)           |                 | 500             |                                      | 2.5         |
| DO-35 (DO-204AH)           |                 | 400             |                                      | 2.5         |
| DO-41 (DO-204AL) (glass)   |                 | 150             |                                      | 2.5         |
| DO-41 (DO-204AL) (plastic) |                 | 100             |                                      | 1           |
| F 126                      |                 | 70              |                                      | 1           |
| micromelf                  |                 |                 | 600                                  | 2.5         |
| SOD-80 (minimelf)          |                 |                 | 600                                  | 2.5         |
| melf                       |                 |                 | 450                                  | 5.0         |
| SOD-110                    |                 |                 | 350                                  | 0.8         |
| SOD-123                    |                 |                 | 600                                  | 1.0         |
| SOD-323                    |                 |                 | 600                                  | 0.7         |
| SOD-523                    |                 |                 | 100                                  | 0.5         |
| SMA                        |                 |                 | 600                                  | 1.8         |
| SMB (DO-214)               |                 |                 | 75                                   | 2.4         |
| SMC (DO-215)               |                 |                 | 25                                   | 5.1         |
| DO-220                     | 3               |                 |                                      | 5.7         |
| SOD-15                     |                 |                 | 20                                   | 5.1         |

### 8.2 Low power diodes

Silicon: signal diodes; PIN; fast and slow recovery rectifier diodes; SCHOTTKY; up to 3A;  
 Thyristors, triacs up to 3A;  
 Zener diodes up to 1,5W;  
 Transient voltage suppressors, up to 5 kW (peak, 10µs/1000µs);  
 Gallium arsenide diodes, up to 0.1W.

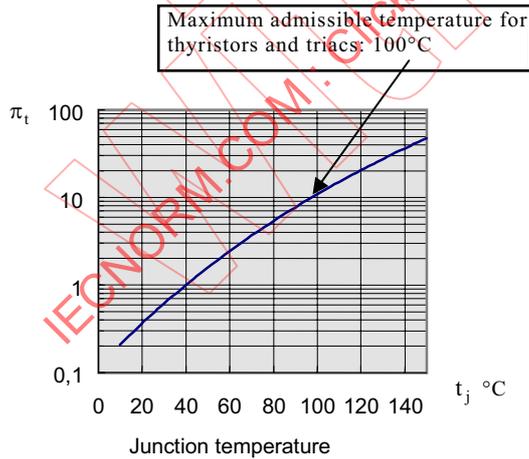
**MATHEMATICAL MODEL**

$$\lambda = \left\{ \underbrace{\pi_U \times \lambda_0}_{\lambda_{die}} \times \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\} + \left\{ \underbrace{2.75 \times 10^{-3} \times \sum_{i=1}^z (\pi_n)_i \times (\Delta T_i)^{0.68}}_{\lambda_{package}} \times \lambda_B \right\} + \left\{ \frac{\pi_I \times \lambda_{EOS}}{\lambda_{overstress}} \right\} \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

$(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.  
 $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.

$\pi_U$  : use factor (permanent or not);  
 $\lambda_0$  : base failure rate of the die. See table on this page;  
 $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the diode mission profile;  
 $\tau_i$  :  $i^{th}$  working time ratio of the diode for the  $i^{th}$  junction temperature of the mission profile;  
 $\tau_{on}$  : total working time ratio of the diode. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$   
 $\tau_{off}$  : time ratio for the diode being in storage (or dormant) mode;  
 $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual number cycles of thermal variations seen by the package, with the amplitude  $\Delta T_i$   
 $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile;  
 $\lambda_B$  : base failure rate of the diode package. See Table 18;  
 $\pi_I$  : influence factor related to the use of the diode (protection interface or not);  
 $\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application.



For protection diodes  $t_j$  = ambient temperature  
 other diodes  $t_j$  = ambient temp. +  $(R_{th} \times P)$

**Mathematical formula for  $\pi_t$**

$$\pi_t = e^{4640 \left( \frac{1}{313} - \frac{1}{t_j + 273} \right)} \quad (0.4 \text{ electron-volt})$$

| Protection diodes as interface;<br>typical calculated values |   |   | $\lambda_{EOS}$<br>FIT | $\pi_I$ |
|--|---|---|------------------------|---------|
| Function   | Electrical environment                      |   |                        |         |
| Protection<br>Interface                                      | Computer                                    |   | 10                     | 1       |
|  | Telecoms                                    | switching                                   | 15                     | 1       |
|  |   | transmitting<br>access,<br>subscriber cards | 40                     | 1       |
|  |   | Subscriber<br>equipment                     | 70                     | 1       |
|  | Railways, payphone                          |   | 100                    | 1       |
|  | Civilian avionics (on board<br>calculators) |   | 20                     | 1       |
|  | Voltage supply, Converters                  |   | 40                     | 1       |
| Non<br>Interfaces  | All electrical environment                  |   |                        | 0       |

| Failure rate for $t_j=40^\circ\text{C}$<br>(expressed in FIT) |                              |                              | $\lambda_0$ |     |
|---|------------------------------|------------------------------|-------------|-----|
| Silicon<br>diodes   | signal (<1A)                 |                              | 0.07        |     |
|   | Recovery, rectifier 1A à 3A  |                              | 0.1         |     |
|   | Zener (regulator) ≤ 1.5 watt |                              | 0.4         |     |
|   | suppressor                   | Transient voltage            |             | 2.3 |
|   |                              | Trigger transient<br>voltage |             | 2   |
| Gallium arsenide diodes (≤ 0.1 W)                             |                              |                              | 0.3         |     |
| Thyristors, triacs (≤ 3A)                                     |                              |                              | 1           |     |

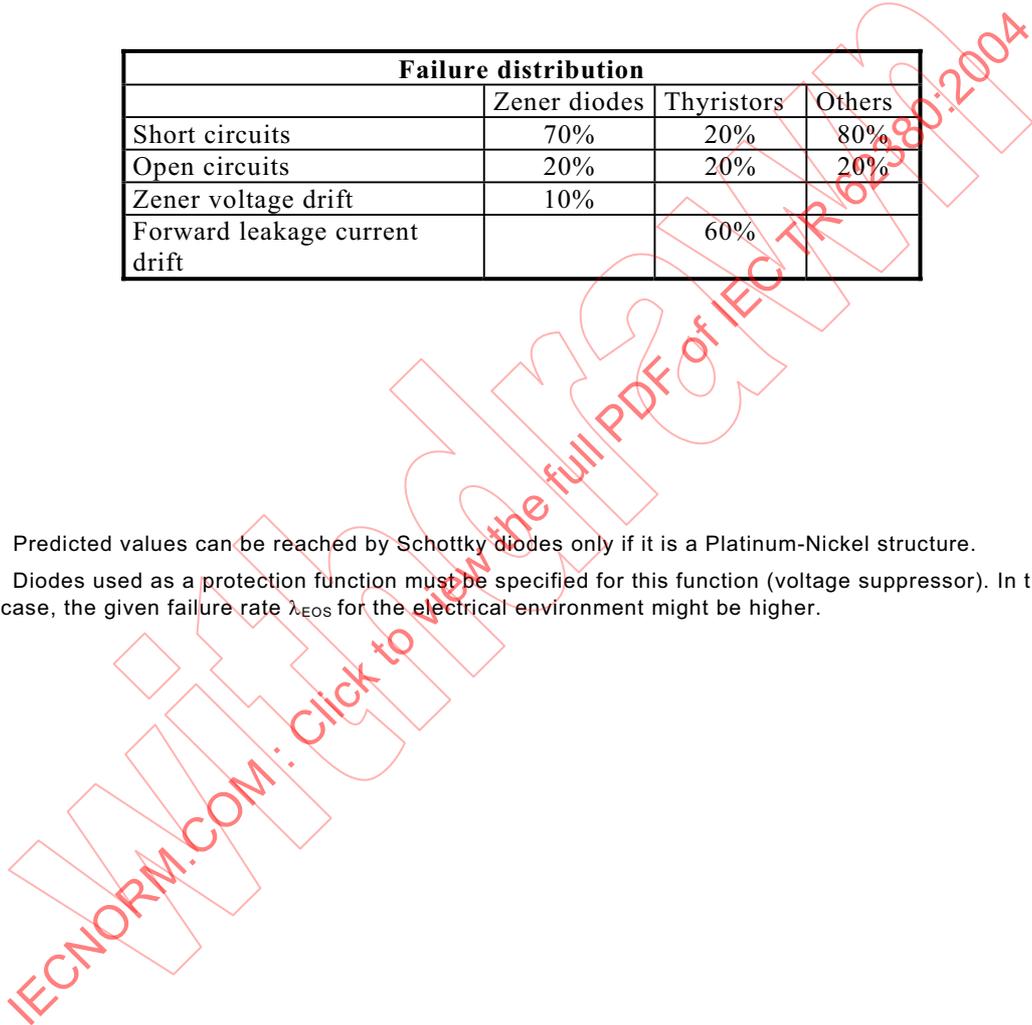
|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the                                  | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$                                    | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ac})_i$                                   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ =average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile. |                                     |

| Type of use  |                                     | $\pi_U$ |
|--|-------------------------------------|---------|
| <b>Thyristors and triacs</b>   | Permanent use*                      | 10      |
|  | Occasional use*<br>(ratio off/on>1) | 1       |
| Other diodes   |                                     | 1       |
| *: The expression "use" corresponds to a switching condition with component reverse biased part of the time . When the component is forward biased permanently, take $\pi_U = 1$ . |                                     |         |

| Failure distribution          |              |            |        |
|-------------------------------|--------------|------------|--------|
|                               | Zener diodes | Thyristors | Others |
| Short circuits                | 70%          | 20%        | 80%    |
| Open circuits                 | 20%          | 20%        | 20%    |
| Zener voltage drift           | 10%          |            |        |
| Forward leakage current drift |              | 60%        |        |

NOTE 1 Predicted values can be reached by Schottky diodes only if it is a Platinum-Nickel structure.

NOTE 2 Diodes used as a protection function must be specified for this function (voltage suppressor). In the contrary case, the given failure rate  $\lambda_{EOS}$  for the electrical environment might be higher.



### 8.3 Power diodes

Silicon: Rectifier diodes; fast recovery rectifier diodes; SCHOTTKY; above 3A.  
 Thyristors, triacs; above 3A.  
 Zener diodes above 1,5 W.  
 Transient voltage suppressors 5 kW (en crête, 10µs/1000µs).  
 Gallium arsenide diodes, above 0,1W.

} excepted modules

#### MATHEMATICAL MODEL

$$\lambda = \left\{ \underbrace{\left\{ \pi_U \times \lambda_0 \right\}}_{\lambda_{die}} \times \underbrace{\left\{ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\}}_{\lambda_{package}} + \left\{ 2.75 \times 10^{-3} \times \sum_{i=1}^y (\pi_n)_i \times (\Delta T_i)^{0.68} \right\} \times \lambda_B \right\} + \left\{ \frac{\pi_I \times \lambda_{EOS}}{\lambda_{overstress}} \right\} \times 10^{-9} / h$$

#### NECESSARY INFORMATION:\*

( $t_{ae}$ )<sub>i</sub> : average outside ambient temperature surrounding the equipment, during the i<sup>th</sup> phase of the mission profile.  
 ( $t_{ac}$ )<sub>i</sub> : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.

$\pi_U$  : use factor (permanent or not).

$\lambda_0$  : base failure rate of the die. See table on this page.

( $\pi_t$ )<sub>i</sub> : i<sup>th</sup> temperature factor related to the i<sup>th</sup> junction temperature of the diode mission profile.

$\tau_i$  : i<sup>th</sup> working time ratio of the diode for the i<sup>th</sup> junction temperature of the mission profile.

$\tau_{on}$  : total working time ratio of the diode. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$

$\tau_{off}$  : time ratio for the diode being in storage (or dormant) mode.

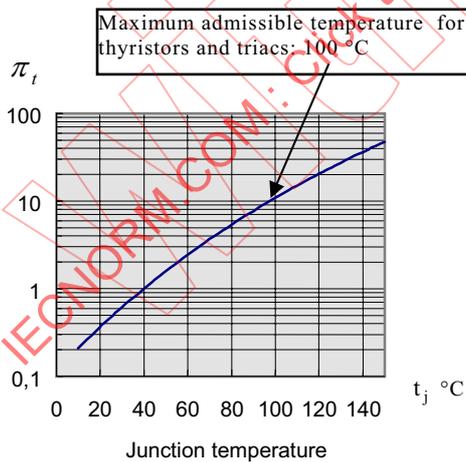
( $\pi_n$ )<sub>i</sub> : i<sup>th</sup> influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .

$\Delta T_i$  : i<sup>th</sup> thermal amplitude variation of the mission profile.

$\lambda_B$  : base failure rate of the diode package. see Table 18.

$\pi_I$  : influence factor related to the use of the diode (protection interface or not).

$\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application..



For protection diodes  $t_j =$  ambient temperature  
 other diodes  $t_j =$  ambient temp.  
 +(R<sub>th</sub> × P)

#### Mathematical formula for $\pi_t$

$$\pi_t = e^{4640 \left( \frac{1}{313} - \frac{1}{t_j + 273} \right)} \quad (0.4 \text{ electron-volt})$$

| Protection diodes as interface;<br>typical calculated values |   |   | $\lambda_{EOS}$<br>FIT | $\pi_I$ |
|--|---|---|------------------------|---------|
| Function   | Electrical environment                      |   |                        |         |
| Protection<br>Interface                                      | Computer                                    |   | 10                     | 1       |
|  | Telecoms                                    | switching                                   | 15                     | 1       |
|  |   | transmitting<br>access,<br>subscriber cards | 40                     | 1       |
|  |   | Subscriber<br>equipment                     | 70                     | 1       |
|  | Railways, payphone                          |   | 100                    | 1       |
|  | Civilian avionics (on board<br>calculators) |   | 20                     | 1       |
|  | Voltage supply, converters                  |   | 40                     | 1       |
| Non<br>Interfaces  | All electrical environment                  |   |                        | 0       |

| Failure rate for $t_j=40^\circ\text{C}$<br>(expressed in FIT) |                             |                   | $\lambda_0$ |
|---|-----------------------------|-------------------|-------------|
| Silicon<br>Diodes   | Recovery , rectifier (>3A)  |                   | 0.7         |
|   | Zener (regulator) >1,5 watt |                   | 0.7         |
|   | suppressor                  | Transient voltage |             |
| Trigger transient<br>voltage                                  |                             |                   | 3           |
| Gallium arsenide diodes (>0,1 w )                             |                             |                   | 1           |
| Thyristors, triacs (>3A)                                      |                             |                   | 3           |

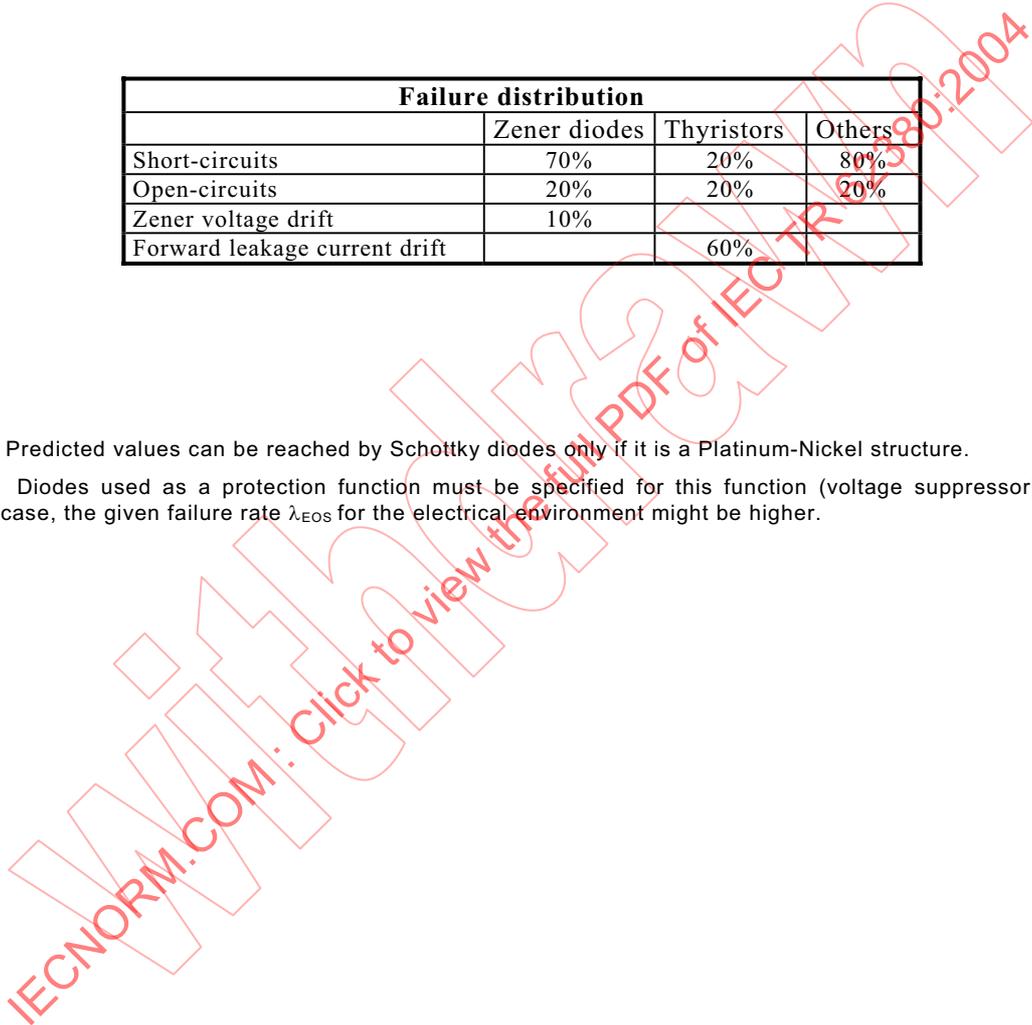
|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the                                  | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$                                    | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ae})_i$                                   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ =average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile. |                                     |

| Type of use   |                                     | $\pi_U$ |
|---|-------------------------------------|---------|
| <b>Thyristors and triacs</b>  | Permanent use*                      | 10      |
|   | Occasional use*<br>(ratio off/on>1) | 1       |
| Other diodes  |                                     | 1       |
| *: The expression " use " corresponds to a switching condition. The component is reverse biased part of the time . When the component is forward biased permanently, take $\Pi_U = 1$ . |                                     |         |

| Failure distribution          |              |            |        |
|-------------------------------|--------------|------------|--------|
|                               | Zener diodes | Thyristors | Others |
| Short-circuits                | 70%          | 20%        | 80%    |
| Open-circuits                 | 20%          | 20%        | 20%    |
| Zener voltage drift           | 10%          |            |        |
| Forward leakage current drift |              | 60%        |        |

NOTE1 Predicted values can be reached by Schottky diodes only if it is a Platinum-Nickel structure.

NOTE 2 Diodes used as a protection function must be specified for this function (voltage suppressor). In the contrary case, the given failure rate  $\lambda_{EOS}$  for the electrical environment might be higher.



### 8.4 Low power transistors

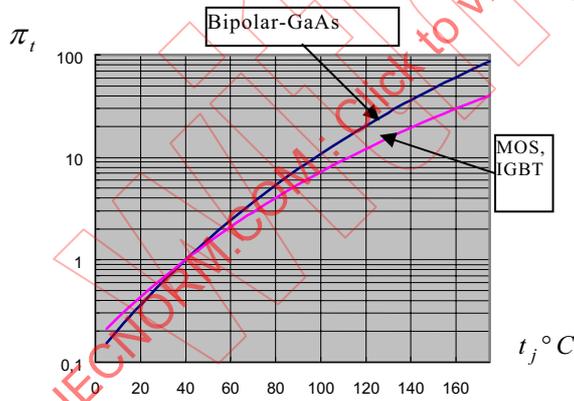
Silicon, junction, FET, MOS; up to 5 W.  
Gallium Arsenide ; up to 1 W.

#### MATHEMATICAL MODEL

$$\lambda = \left\{ \underbrace{\pi_S \times \lambda_0}_{\lambda_{die}} \times \underbrace{\left\{ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\}}_{\lambda_{package}} + \underbrace{2.75 \times 10^{-3} \times \left( \sum_{i=1}^z (\pi_n)_i \times (\Delta T_i)^{0.68} \right)}_{\lambda_{package}} \times \lambda_B + \underbrace{\left\{ \pi_I \times \lambda_{EOS} \right\}}_{\lambda_{overstress}} \right\} \times 10^{-9} / h$$

#### NECESSARY INFORMATION:

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $\pi_S$  : charge factor.
- $\lambda_0$  : base failure rate of the die. See table on this page.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the transistor mission profile.
- $\tau_i$  :  $i^{emc}$  working time ratio of the transistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the transistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the transistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- $\lambda_B$  : base failure rate of the transistor package. See Table 18.
- $\pi_I$  : influence factor related to the use of the transistor (protection interface or not).
- $\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application..

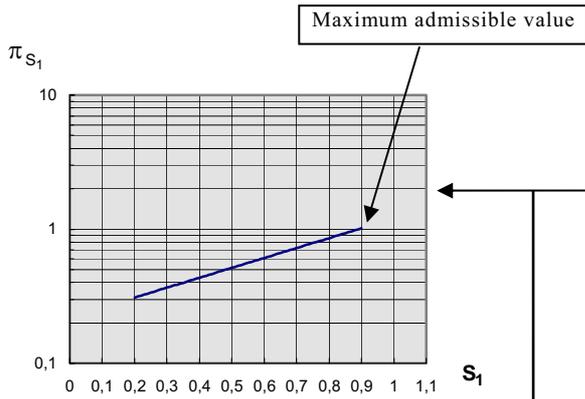


| Protection transistor as interface;<br>typical calculated values |  |                                       | $\lambda_{EOS}$ | $\pi_I$ |
|--|--|---------------------------------------|-----------------|---------|
| Function   | Electrical environment                   |                                       | FIT             |         |
| Protection Interface   | Computer                                 |                                       | 10              | 1       |
|  | Telecoms                                 | switching                             | 15              | 1       |
|  |  | transmitting access, subscriber cards | 40              | 1       |
|  |  | Subscriber equipment                  | 70              | 1       |
|  | Railways, payphone                       |                                       | 100             | 1       |
|  | Civilian avionics (on board calculators) |                                       | 20              | 1       |
|  | Voltage supply, converters               |                                       | 40              | 1       |
| Non Interfaces   | All electrical environment               |                                       |                 | 0       |

| Mathematical formulas for $\pi_t$ and $\pi_S$ |               |  |
|---|---------------|--|
| $\pi_t$                                       | Bipolar GaAs  | $\pi_t = e^{4640 \left( \frac{1}{373} - \frac{1}{t_j + 273} \right)}$<br>(activation energy: 0.4 eV) |
|   | MOS IGBT      | $\pi_t = e^{3480 \left( \frac{1}{373} - \frac{1}{t_j + 273} \right)}$<br>(activation energy: 0.3 eV) |
| $\pi_S$                                       | FET, MOS IGBT | $\pi_{S1} = 0.22e^{1.7S_1}$<br>$\pi_{S2} = 0.22e^{3S_2}$   |
|   | Bipolar       | $\pi_S = 0.22e^{1.7S}$   |

| Failure rate for $t_j=40^\circ C$<br>(expressed in FIT)   |  | $\lambda_0$ |
|---|--|-------------|
| Silicon transistors   |  | 0,75        |
| <ul style="list-style-type: none"> <li>• Bipolar; npn; pnp</li> <li>• MOS p, n ; FET</li> </ul> |  |             |
| Gallium Arsenide transistors  |  | 0,3         |

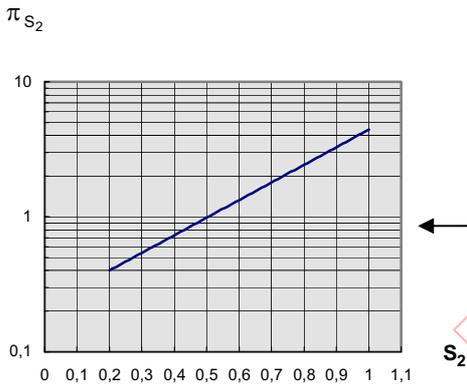
|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the                                  | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$                                    | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ac})_i$                                   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |



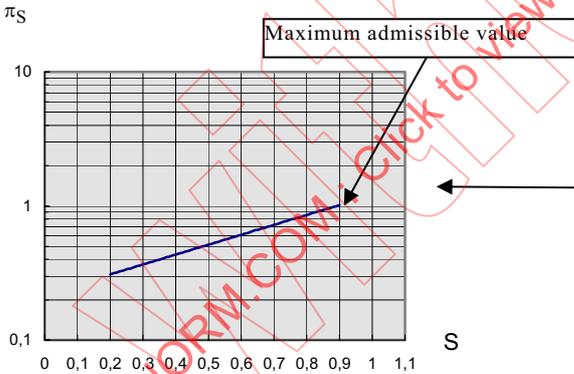
**FET, MOS:**  
 $\pi_S = \pi_{S_1} \times \pi_{S_2}$

$$S_1 = \frac{\text{Maximum repetitive applied } V_{DS} \text{ voltage}}{\text{Minimum specified } V_{DS} \text{ voltage}}$$

- $S_2$  is accepted up to 1 since the destructive gate oxide voltage value is normally three times greater than the maximum rated  $V_{GS}$  voltage (for MOS transistors).
- These values (maximum and destructive  $V_{GS}$  values) shall be checked during the qualification process. For instance, if the maximum rated  $V_{GS}$  voltage is 20 V, the destructive  $V_{GS}$  voltage value must be greater than 60 V (practically between 60 V and 80 V).



$$S_2 = \frac{\text{Maximum repetitive applied } V_{GS} \text{ voltage}}{\text{Minimum specified } V_{GS} \text{ voltage}}$$



**BIPOLAR**

$$S = \frac{\text{Maximum repetitive applied } V_{CE} \text{ voltage}}{\text{Minimum specified } V_{CE} \text{ breakdown voltage}}$$

- Fragile assembly:**
- 1 - Cavity package weighting more than 0,1 g
  - 2 - Package weighting more than 0,1g and fixed by leads (more than 2 mm)
- Strong assembly:**
- 1 - Molded plastic components (lead less than 2 mm) or DIL, or surface mounted component (SMT)
  - 2 - Firmly fixed packages (screw, clips, glue)
  - 3 - Components weighting more than 0,1 g

| Failure distribution |                | %  |
|----------------------|----------------|----|
| Silicon              | Short-circuits | 85 |
|                      | Open-circuits  | 15 |
| Gallium - arsenide   | Short-circuits | 95 |
|                      | Open-circuits  | 5  |

### 8.5 Power transistors

Silicon: 5 W or more  
Gallium arsenide: 1 W or more

{ Excepted modules

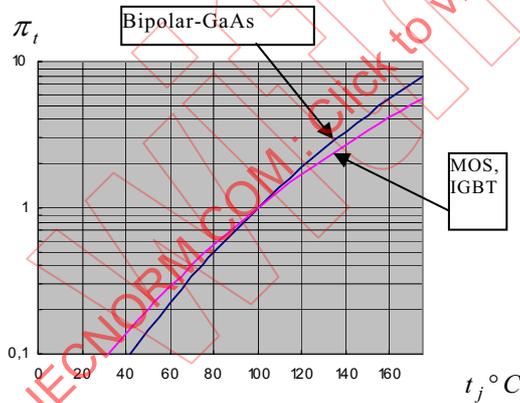
**CAUTION !**  
Under cyclic operation, the life time is limited !

#### MATHEMATICAL MODEL

$$\lambda = \left\{ \underbrace{\pi_S \times \lambda_0}_{\lambda_{die}} \times \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\} + \left\{ \underbrace{2.75 \times 10^{-3} \times \sum_{i=1}^z (\pi_n)_i \times (\Delta T_i)^{0.68}}_{\lambda_{package}} \times \lambda_B \right\} + \left\{ \frac{\pi_I \times \lambda_{EOS}}{\lambda_{overstress}} \right\} \times 10^{-9} / h$$

#### NECESSARY INFORMATION:

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $\pi_S$  : charge factor.
- $\lambda_0$  : base failure rate of the die. See table on this page.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the transistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the transistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the transistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the transistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- $\lambda_B$  : base failure rate of the transistor package. See Table 18.
- $\pi_I$  : influence factor related to the use of the transistor (protection interface or not).
- $\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application.

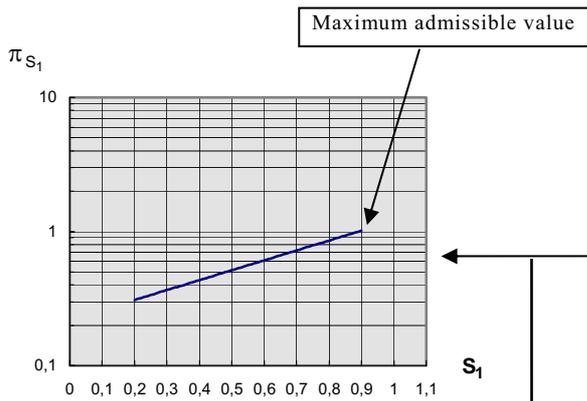


| Protection transistor as interface;<br>typical calculated values |  |                                       | $\lambda_{EOS}$ | $\pi_I$ |
|--|--|---------------------------------------|-----------------|---------|
| Function   | Electrical environment                   |                                       | FIT             |         |
| Protection Interface   | Computer                                 |                                       | 10              | 1       |
|  | Telecoms                                 | switching                             | 15              | 1       |
|  |  | transmitting access, subscriber cards | 40              | 1       |
|  |  | Subscriber equipment                  | 70              | 1       |
|  | Railways, payphone                       |                                       | 100             | 1       |
|  | Civilian avionics (on board calculators) |                                       | 20              | 1       |
|  | Voltage supply, converters               |                                       | 40              | 1       |
| Non Interfaces   | All electrical environment               |                                       |                 | 0       |

| Failure rate for $t_j=100\text{ }^\circ\text{C}$<br>(expressed in FIT) | $\lambda_0$ |
|--|-------------|
| Silicon transistors  | 2           |
| • Bipolar; npn; pnp  |             |
| • MOS p, n ; FET   |             |
| Gallium Arsenide transistors   | 1           |

| Mathematical formulas for $\pi_t$ and $\pi_S$ |                 |   |
|---|-----------------|---|
| $\pi_t$                                       | Bipolar<br>GaAs | $\pi_t = e^{4640(\frac{1}{373} - \frac{1}{t_j+273})}$<br>(activation energy : 0.4 ev) |
|   | MOS<br>IGBT     | $\pi_t = e^{3480(\frac{1}{373} - \frac{1}{t_j+273})}$<br>(activation energy : 0.3 ev) |
| $\pi_S$                                       | FET, MOS        | $\pi_{S1} = 0.22e^{1.7S_1}$   |
|   | IGBT            | $\pi_{S2} = 0.22e^{3S_2}$   |
|   | Bipolar         | $\pi_S = 0.22e^{1.7S}$  |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the                                  | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$                                    | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ac})_i$                                     |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})_i$ variation, during the $i^{th}$ phase of the mission profile |                                     |



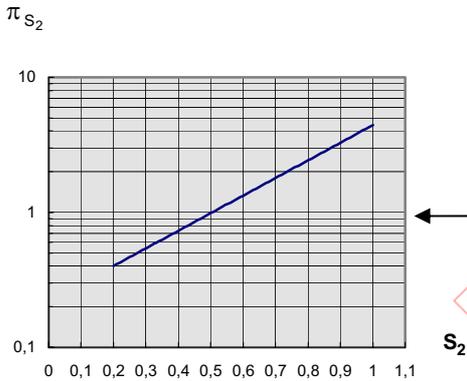
**Life expectancy**  
 Under cyclic operation, the number of cycles is limited to:  

$$N = 10^7 e^{-0.05\Delta t_j}$$
  
 $\Delta t_j$  : junction temperature range

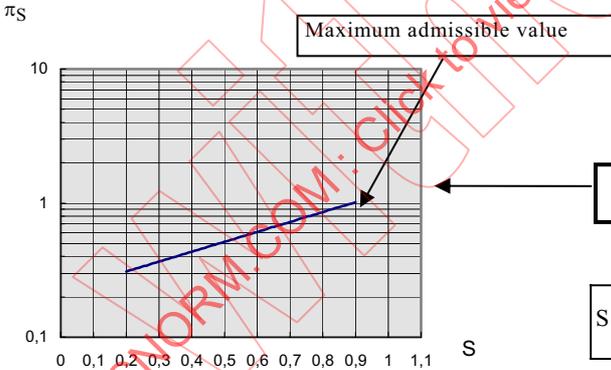
**FET, MOS:**  
 $\pi_S = \pi_{S_1} \times \pi_{S_2}$

$$S_1 = \frac{\text{Maximum repetitive applied } V_{DS} \text{ voltage}}{\text{Minimum specified } V_{DS} \text{ voltage}}$$

- $S_2$  is accepted up to 1 since the destructive gate oxide voltage value is normally three times greater than the maximum rated  $V_{GS}$  voltage (for MOS transistors).
- These values (maximum and destructive  $V_{GS}$  values) shall be checked during the qualification process. For instance, if the maximum rated  $V_{GS}$  voltage is 20 V, the destructive  $V_{GS}$  voltage value must be greater than 60 V (practically between 60 V and 80 V).



$$S_2 = \frac{\text{Maximum repetitive applied } V_{GS} \text{ voltage}}{\text{Minimum specified } V_{GS} \text{ voltage}}$$



**BIPOLAR**

$$S = \frac{\text{Maximum repetitive applied } V_{CE} \text{ voltage}}{\text{Minimum specified } V_{CE} \text{ breakdown voltage}}$$

- Fragile assembly:**
- 1 - Cavity package weighting more than 0,1 g
  - 2 - Package weighting more than 0,1 g and fixed by leads (more than 2 mm)
- Strong assembly:**
- 1 - Molded plastic components (lead less than 2 mm) or DIL, or surface mounted component (SMT)
  - 2 - Firmly fixed packages (screw, clips, glue)
  - 3 - Components weighting more than 0,1 g

| Failure distribution |                | %  |
|----------------------|----------------|----|
| Silicon              | Short-circuits | 85 |
|                      | Open-circuits  | 15 |
| Gallium - arsenide   | Short-circuits | 95 |
|                      | Open-circuits  | 5  |

### 8.6 Optocouplers

#### 8.6.1 Life expectancy

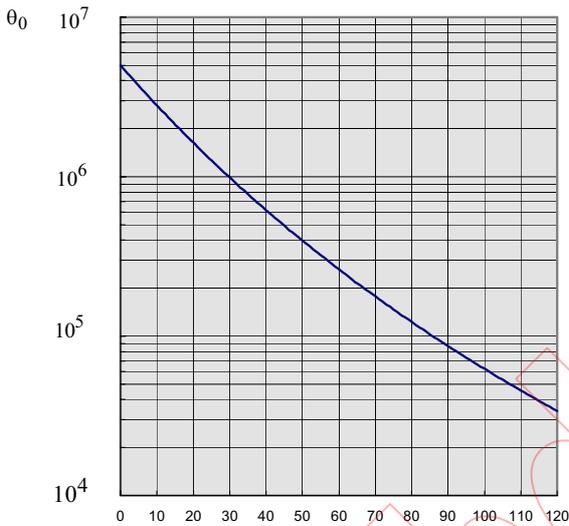
The operating time must not exceed the life expectancy value  $\theta$ . Beyond this time, the failure rate  $\lambda$  cannot be assumed to be constant.

$$\theta = \theta_0 \times \kappa_0 \times \kappa_1 \times \kappa_2 \times \kappa_3 \text{ h}$$

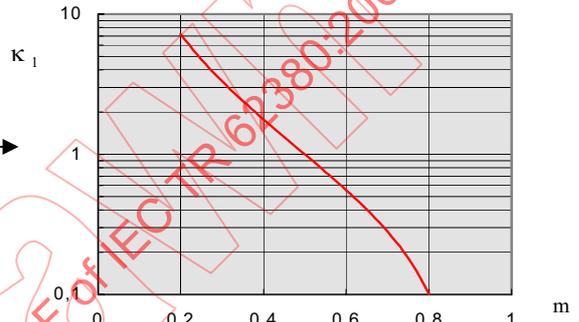
For molded plastic optocouplers, the temperature junction must not exceed 90 °C

| Necessary information                        | For                  |
|--|----------------------|
| Junction temperature $t_j$                   | $\theta_0$           |
| Input current (operating and test condition) | $\kappa_0, \kappa_2$ |
| Initial, final transfer ratio                | $\kappa_1$           |

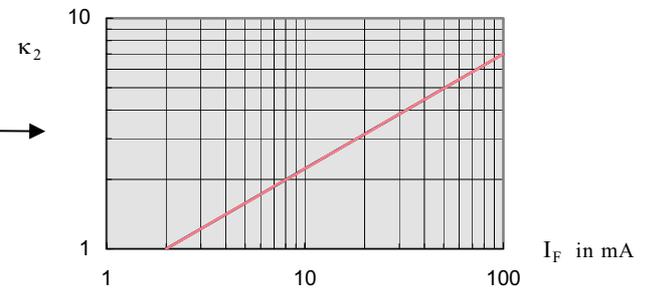
$$\kappa_0 = \frac{50}{\text{input current (operating, mA)}}$$



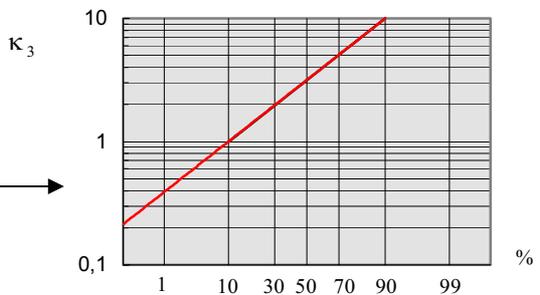
Life expectancy in hours = f(junction temperature  $t_j$ )



$$\kappa_1 \text{ according to the selected ratio } m = \frac{\text{Final transfer ratio}}{\text{Initial transfer ratio}}$$



$\kappa_2$  according to the measured current  $I_F$  of the transfer ratio (testing conditions).



$\kappa_3$  for a cumulative failure ratio different from 10 %.

**Optocoupler life expectancy  $\theta_0$**  according to the junction temperature and the following failure criterion:

- Transfer ratio measurement conditions  
 $V_{CE} = 5 \text{ volts } I_F = 2 \text{ mA}$   
 $\frac{\text{Final transfer ratio}}{\text{Initial transfer ratio}} = m = 0.5$
- For an operating current of 50 mA

**Note** The life expectancy is estimated for a cumulative failure ratio of 10 %.

| Life expectancy $\theta_0$    |
|-------------------------------|
| $0.4e^{\frac{4640}{t_j+273}}$ |

8.6.2 Failure rate

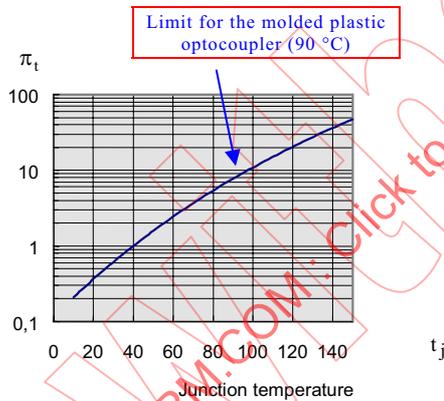
MATHEMATICAL MODEL

$$\lambda = \left\{ \underbrace{2.2 \times \pi_S}_{\lambda_{die}} \times \underbrace{\left\{ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right\}}_{\lambda_{package}} + \left\{ 2.75 \times 10^{-3} \times \sum_{i=1}^z (\pi_n)_i \times (\Delta T_i)^{0.68} \right\} \times \lambda_B + \left\{ \frac{\pi_I \times \lambda_{EOS}}{\lambda_{overstress}} \right\} \right\} \times 10^{-9} / h$$

**CAUTION !**  
Life expectancy is limited !

NECESSARY INFORMATION:

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $\pi_S$  : charge factor.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the optocoupler mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the optocoupler for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the optocoupler. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the optocoupler being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- $\lambda_B$  : base failure rate of the optocoupler package. See Table 18.
- $\pi_I$  : influence factor related to the use of the optocoupler (interface or not).
- $\lambda_{EOS}$  : failure rate related to the electrical overstress in the considered application.



$t_j = \text{ambient temperature} + (\text{power dissipation}) \times R_{ja}$   
\* emitter + receiver

$\frac{V_{io}}{V_{ioRM}}$  permanent applied voltage (input/output)\*  
peak, repetitive insulation voltage  
\* without considering partial discharges.

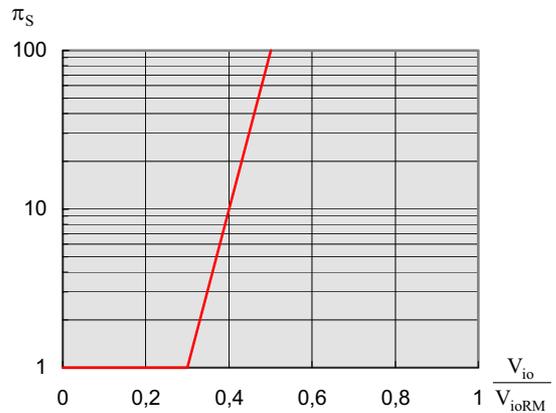
| Failure distribution |      |
|----------------------|------|
| Open circuits        | 50 % |
| Short circuits       | 10 % |
| Drift                | 40 % |

**Mathematical formula  $\pi_t$**

$$\pi_t = e^{\frac{4640}{313} \left( \frac{1}{t_j} - \frac{1}{273} \right)}$$

(activation energy : 0.4 ev)

| Optocoupler as interface;<br>typical calculated values |  |                                       | $\lambda_{EOS}$ | $\pi_I$ |
|--|--|---------------------------------------|-----------------|---------|
| Function   | Electrical environment                   |                                       | FIT             |         |
| Protection<br>Interface                                | Computer                                 |                                       | 10              | 1       |
|  | Telecoms                                 | switching                             | 15              | 1       |
|  |  | transmitting access, subscriber cards | 40              | 1       |
|  |  | Subscriber equipment                  | 70              | 1       |
|  | Railways, payphone                       |                                       | 100             | 1       |
|  | Civilian avionics (on board calculators) |                                       | 20              | 1       |
| Non Interfaces   | Voltage supply, converters               |                                       | 40              | 1       |
|  | All electrical environment               |                                       |                 | 0       |



Influence of the applied voltage between input-output

|   |   |                                     |
|---|---|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year  | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year   | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |   |                                     |
| For an on/off phase   | $\Delta T_i = \left[ \frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ac})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ =average per cycle of the $(t_{ac})$ variation, during the $i^{\text{th}}$ phase of the mission profile. |                                     |

IECNORM.COM: Click to view the full PDF of IEC TR 62380:2004

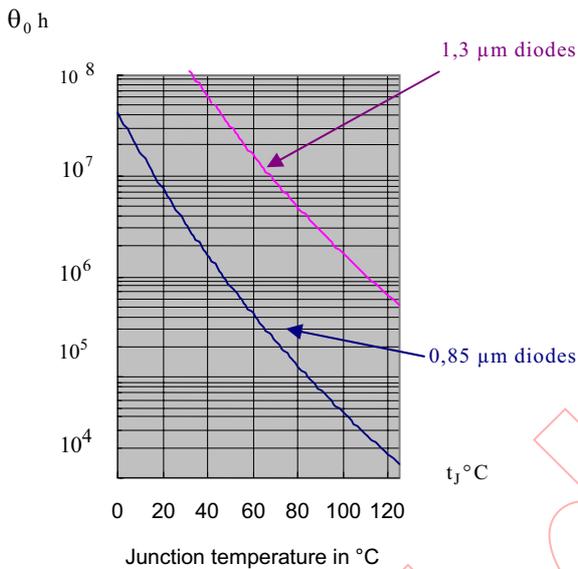
## 9 Optoelectronics

NOTE Optical component failure rates in this clause are only given for the ground fixed environment, with a permanent working mission profile, and a daylight-night thermal cycling of less than 3 °C.

### 9.1 Light emitting diodes diode modules (IEC 60747-12-2, IEC 62007)

#### 9.1.1 Life expectancy

$$\theta = \theta_0 \times \kappa_0 \times \kappa_1 \times \kappa_2 \times \kappa_3 \text{ h}$$



Life expectancy  $\theta_0$  of a LED according to the junction temperature  $t_j$

- For an operating current of 100 mA
- For the failure criterion:

$$m = \frac{\text{Final optical power}}{\text{Initial optical power}} = 0,5$$

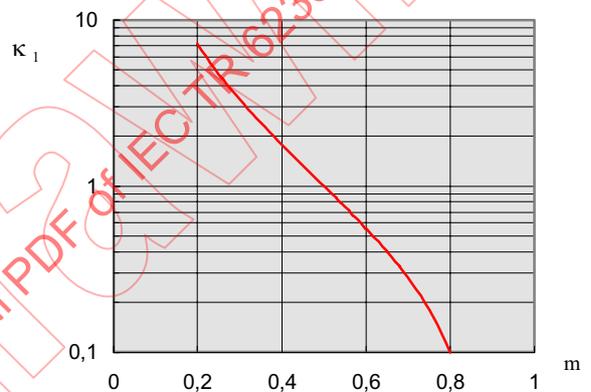
(with an optical power measuring current equal to 100 mA)

NOTE The life expectancy  $\theta_0$  is evaluated for a cumulative failure ratio of 10 %.

The operating time must not exceed the life expectancy value  $\theta$ . Beyond this time the failure rate  $\lambda$  cannot be assumed to be constant.

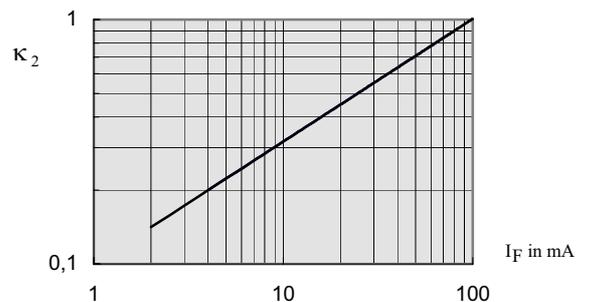
| Necessary information                   |       | For        |
|---|-------|------------|
| Junction temperature                    | $t_j$ | $\theta_0$ |
| Operating current                       |       | $\kappa_0$ |
| Measurement current (for optical power) |       | $\kappa_2$ |

$$\kappa_0 = \frac{100}{\text{operating input current (mA)}}$$

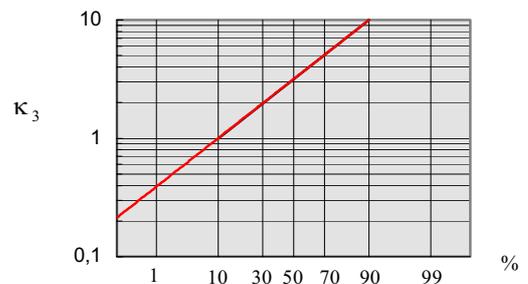


$\kappa_1$  according to the selected ratio m:

$$\text{with } m = \frac{\text{Final optical power}}{\text{Initial optical power}}$$



$\kappa_2$  according to the optical power measuring current



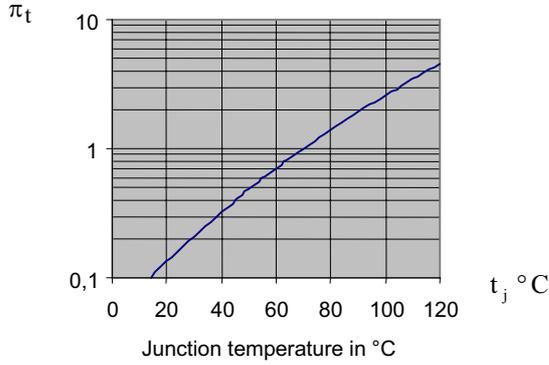
$\kappa_3$  for a cumulative failures different from 10 %

| Diode types               | Life expectancy $\theta_0$ expressed in hours  |
|---------------------------|--|
| 0,85 $\mu\text{m}$ diodes | $2,3 \times 10^5 e^{7000 \left( \frac{1}{t_j + 273} - \frac{1}{343} \right)}$ (0,6 eV) |
| 1,3 $\mu\text{m}$ diodes  | $8,7 \times 10^6 e^{7000 \left( \frac{1}{t_j + 273} - \frac{1}{343} \right)}$ (0,6 eV) |

9.1.2 Failure rate (Modules datacom)

**MATHEMATICAL MODEL**  
 $\lambda = \lambda_0 \times \pi_t \times 10^{-9} \text{ /h}$

**CAUTION !**  
 The life expectancy is limited !



| Necessary information |                | for            |
|-----------------------|----------------|----------------|
| Junction temperature  | t <sub>j</sub> | π <sub>t</sub> |
| Module type           |                | λ <sub>0</sub> |

**Temperature influence**

$t_j = t_c + R_{th} \times P$   
 P = applied power  
 t<sub>c</sub> = case temperature  
 R<sub>th</sub> = thermal resistance (junction/case)

- measured
- or rated
- by default, 150°C/W

| Module type  | λ <sub>0</sub> FIT |
|--|--------------------|
| Elementary emitter module with fibered DEL without electronic                                  | 100                |
| Emitter module with fibered DEL and DEL driver   | 130                |
| Emitter / receiver module with fibered DEL + PIN + electronics with or without clock recovery. | 180                |
| Emitter / receiver module with fibered DEL +APD + electronics with or without clock recovery   | 200                |

**Mathematical formula for π<sub>t</sub>**  
 $\pi_t = e^{4060 \left( \frac{1}{343} - \frac{1}{t + 273} \right)}$  (activation energy: 0.35eV)

| Failure distribution according to package type | With window | With fibre |
|--|-------------|------------|
| Short circuit (forward degradation)            | 70%         | 40%        |
| Open   | 10%         | 10%        |
| Optical coupling, or fiber                     | 20%         | 50%        |

$\theta = \theta_0 \cdot \kappa_1 \cdot \kappa_2$  in hours

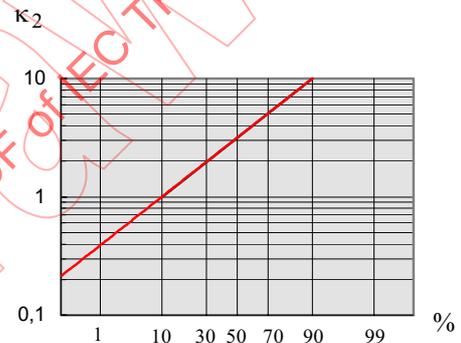
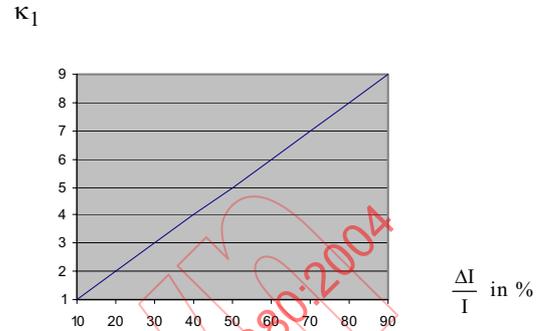
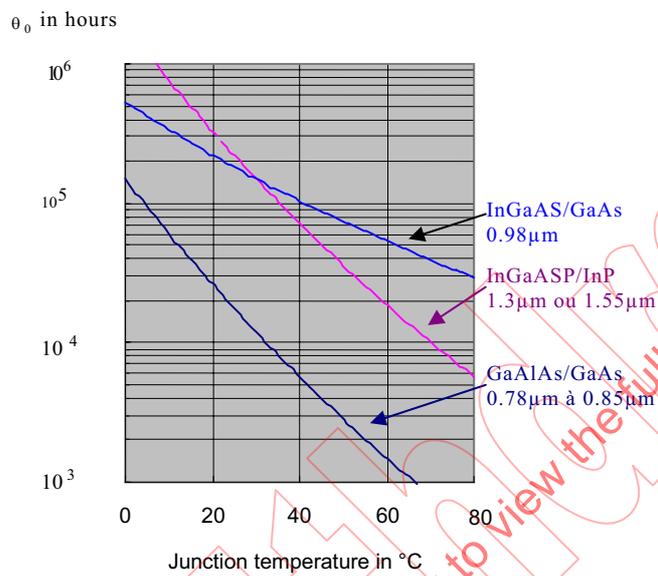
$\kappa_1$  is function of the failure criterion, which is the shift of the operating current at constant optical power,  $\frac{\Delta I}{I}$  in %

- For emitter laser of numerical systems and pump lasers, take a criterion of 50%
- For emitter laser of analog systems and WDM, take 10%

$\kappa_2$  is function of the cumulative failures at the life expectancy value.

- Take generally 10%

The failure rate  $\lambda$  is assumed to be constant (after the infant mortality time), but only within the life expectancy limit  $\theta$ .



| Diode Types  | Life expectancy $\theta_0$  |
|--|---|
| GaAlAs/GaAs diode (0.78 $\mu\text{m}$ ; 0.85 $\mu\text{m}$ )<br>(0.6 eV) | $4 \times 10^3 e^{7000 \left( \frac{1}{t_j+273} - \frac{1}{318} \right)}$   |
| InGaAsP/InP diodes (1.2 $\mu\text{m}$ ; 1.6 $\mu\text{m}$ )<br>(0.6 eV)  | $1.5 \times 10^5 e^{7000 \left( \frac{1}{t_j+273} - \frac{1}{303} \right)}$ |
| InGaAs/GaAs diodes (0.98 $\mu\text{m}$ )<br>(0.3 eV)                     | $1.5 \times 10^5 e^{3500 \left( \frac{1}{t_j+273} - \frac{1}{303} \right)}$ |

**Note:** LASER diodes are sensitive to electrostatic discharges (ESD), consequently their reliability is reduced, even with a low discharge.

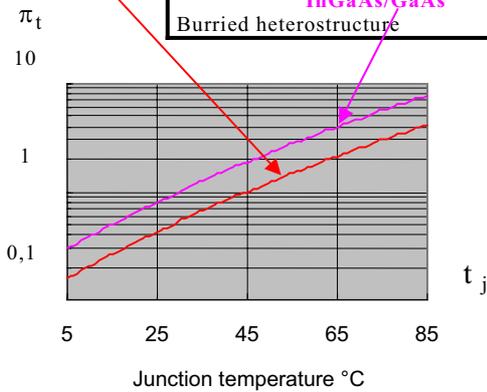
### 9.2 Laser diodes modules - Failure rate

**MATHEMATICAL MODEL**  
 $\lambda = \lambda_0 \times \pi_t \times 10^{-9} \text{ /h}$

**CAUTION !**  
 The life expectancy is limited !

- GaAlAs/ GaAs**
- gain guiding (transmitting ; 0,84  $\mu\text{m}$ )
  - index guiding (compact disks ; 0,8  $\mu\text{m}$  ; with window)

- InGaAs/InP**  
 Burried heterostructure ; Pérot-Fabry or distributed feedback (DFB) 1,3  $\mu\text{m}$  or 1,55  $\mu\text{m}$
- InGaAs/GaAs**  
 Burried heterostructure



**Temperature influence**

$t_j = (\text{submount or case temperature}) + R_{th} \times (P_e - P_0)$   
 $R_{th} =$  thermal resistance (junction/case or junction/submount)  
 $P_e =$  applied electrical power (W)  
 $P_0 =$  optical power (W) (two facets)

| Mathematical formulas for $\pi_t$ |   |
|-----------------------------------|---|
| GaAlAs/GaAs                       | $\pi_t = e^{\frac{4060}{318} \left( \frac{1}{t_j} - \frac{1}{t_j+273} \right)}$ |
| InGaAsP/InP                       | $\pi_t = e^{\frac{4060}{303} \left( \frac{1}{t_j} - \frac{1}{t_j+273} \right)}$ |
| InGaAs/GaAs                       | $\pi_t = e^{\frac{4060}{303} \left( \frac{1}{t_j} - \frac{1}{t_j+273} \right)}$ |

| Necessary information                 | For                 |
|---------------------------------------|---------------------|
| Junction temperature                  | $t_j$               |
| Type of material, internal structure. | $\pi_t ; \lambda_0$ |
| Type of module                        | $\lambda_0$         |

| Material    | Window $\mu\text{m}$ | Module type   | $\lambda_0$ FIT |
|-------------|----------------------|---|-----------------|
| GaAlAs/GaAs | 0,8                  | Elementary emitter modules *  | 3 000           |
| InGaAs/InP  | 1,2 to 1,6           | Elementary emitter modules * without electronics  | 40              |
| InGaAs/InP  | 1,2 to 1,6           | Emitter module with electronics.  | 60              |
| InGaAs/InP  | 1,2 to 1,6           | Emitter/receiver module, with laser PIN and electronics, with or without clock recovery (without crystal) | 80              |
| InGaAs/InP  | 1,2 to 1,6           | Integrated modulator laser module   | 100             |
| InGaAs/InP  | 1,48                 | Pump laser module Power $\leq 250$ mW   | 200             |
| InGaAs/InP  | 1,48                 | Pump laser module Power $> 250$ mW.   | 350             |
| InGaAs/GaAs | 0,98                 | Pump laser module   | 300             |

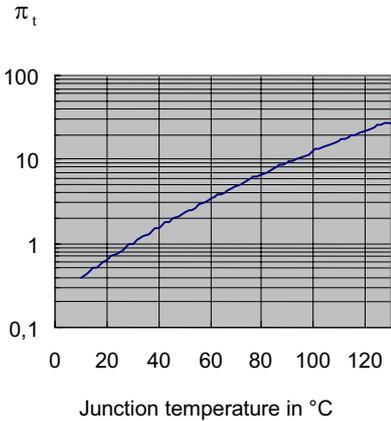
\* Generally an elementary laser module is made of a control photodiode, a laser diode and a coupling element. For other more complex structures, the failure rates mentioned in this table, include all the other elements excepted the thermoelectric cooler and the thermistor.

| Failure modes according to the module type                                |                  |  |                              |                        |
|---|------------------|--|------------------------------|------------------------|
| 1,3 $\mu\text{m}$ /1,55 $\mu\text{m}$ modules<br>(monomode fibre 9 / 125) | diodes failure   | <ul style="list-style-type: none"> <li>Degradation of the spectrum</li> <li>Current increase</li> </ul>                          | 10 %                         |                        |
|   | Coupling failure | <ul style="list-style-type: none"> <li>High drop in output power</li> </ul>  | 90 %                         |                        |
| Pump laser modules<br>(0,98 $\mu\text{m}$ 1,48 $\mu\text{m}$ )            | Diodes failure   | <ul style="list-style-type: none"> <li>High current increase</li> </ul>  | 90 %                         |                        |
|   | Coupling failure | <ul style="list-style-type: none"> <li>High drop in output power</li> </ul>  | 10 %                         |                        |
| 0,85 $\mu\text{m}$ modules<br>(monomode fibre 9 / 125)                    | Diodes failure   | <ul style="list-style-type: none"> <li>No laser effect</li> <li>Degradation of the spectrum</li> <li>Current increase</li> </ul> | Modules transmission<br>80 % | Compact disks<br>100 % |
|   | Coupling failure | <ul style="list-style-type: none"> <li>High drop in output power</li> </ul>  | 10 %                         | 0 %                    |
|   | Broken fibre     | <ul style="list-style-type: none"> <li>No output power</li> </ul>  | 10 %                         | 0 %                    |

**9.3 Photodiodes and receiver modules for telecommunications (IEC 60747-12)**

**MATHEMATICAL MODEL**  
 $\lambda = \lambda_0 \times \pi_t \times 10^{-9} \text{ /h}$

| Necessary information                    | For         |
|--|-------------|
| Junction temperature $t_j$               | $\pi_t$     |
| Type (silicon, GaAlAs, PIN, APD, module) | $\lambda_0$ |



Junction temperature  $t_j$  is admitted to be equal to the ambient temperature

**Temperature influence**

| Type  | $\lambda_0$ FIT  |     |
|---|--|-----|
| <b>PIN diodes</b>                                       | Silicon (0,7 $\mu\text{m}$ - 1,1 $\mu\text{m}$ window) | 5   |
|   | InGaAs (1,2 $\mu\text{m}$ - 1,6 $\mu\text{m}$ window)  | 10  |
| <b>APD diodes (avalanche)</b>                           | Silicon  | 20  |
|   | Germanium  | 40  |
|   | InGaAs   | 80  |
| PIN module + electronics with or without clock recovery |  | 30  |
| APD module + electronics with or without clock recovery |  | 100 |

**Mathematical formula for  $\pi_t$**

$$\pi_t = e^{4060 \left( \frac{1}{303} - \frac{1}{t+273} \right)}$$

0.35 electron-volt

| Failure modes according to package types | With window | With fibre |
|--|-------------|------------|
| Short-circuit (reverse degradation)      | 80 %        | 40 %       |
| Open circuit                             | 20 %        | 10 %       |
| Coupling                                 | 0 %         | 50 %       |

### 9.4 Passive optic components

|   |
|---|
| MATHEMATICAL MODEL                              |
| $\lambda = \lambda_0 \times 10^{-9} \text{ /h}$ |

NOTE Cycling temperature effects on these components is not really known.  $\lambda_0$  values are given for a ground fixed environment and a constant temperature comprised between 20 °C and 40 °C.

| Component types                               |  | $\lambda_0$ in FIT |
|---|--|--------------------|
| Attenuators                                   | Bulk                                   | 2                  |
|   | Fusion splice (attenuation ≤ 10db)     | 2                  |
|   | Fusion splice (attenuation > 10db)     | 10                 |
|   | Pasted splice                          | 10                 |
| Fusing - stretching couplers                  | 1 to 2                                 | 25                 |
|   | 1 to n, with n ≤ 5                     | 50                 |
| Integrated optical couplers                   | 1 to n                                 | 60                 |
| Multiplexer / demultiplexer                   | Fusing - stretching 1 to 2             | 25                 |
|   | Fusing - stretching 1 to n             | 50                 |
|   | Micro-optic                            | 60                 |
| Connectors                                    | 1 optical contact                      | 5                  |
| Jumper or optical cord                        | 2 optical contacts and fibre           | 10                 |
| Optical fibre (cable)                         | For 100 km or per section (any length) | 500                |
| Doped optical fibre, Si matrix. (5 m to 30 m) | Per section, any length                | 1                  |

### 9.5 Miscellaneous optic components

|   |
|---|
| MATHEMATICAL MODEL                              |
| $\lambda = \lambda_0 \times 10^{-9} \text{ /h}$ |

NOTE Cycling temperature effects on these components is not really known.  $\lambda_0$  values are given for a ground fixed environment and a constant temperature comprised between 20 °C and 40 °C.

| Components types            |                               | $\lambda_0$ in FIT |
|-----------------------------|-------------------------------|--------------------|
| LiNbO3 modulator            |                               | 1000               |
| Isolator                    |                               | 10                 |
| Accordable filter           |                               | 330*               |
| Bragg array filter          |                               | 15                 |
| Optical commutator          | Electromechanical with mirror | 200                |
|                             | Integrated with prism         | 200                |
| VCSEL 840 nm                |                               | 300*               |
| Trench reception photodiode |                               | tbd                |
| Phasor                      |                               | tbd                |
| Monolithic duplexor         |                               | tbd                |
| Thermoelectric cooler       |                               | 20                 |
| Thermistor                  |                               | 0.34               |

\*Values are given for a starting production.

## 10 Capacitors and thermistors (NTC)

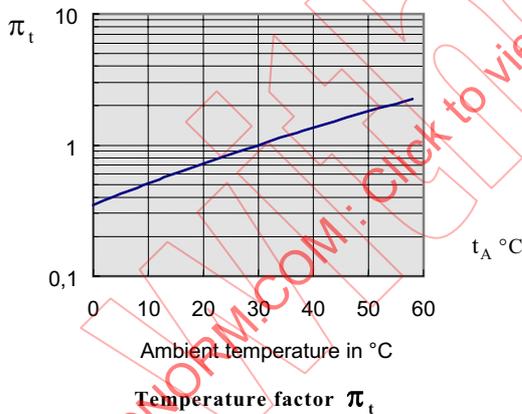
### 10.1 Fixed plastic, paper, dielectric capacitors - Radio interference suppression capacitors (plastic, paper)

#### MATHEMATICAL MODEL

$$\lambda = 0.1 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

#### NECESSARY INFORMATION:

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note\*
- Peak value of the alternative voltage applied to the capacitor See note\*
- Rated voltage of the capacitor. See note\*



| Failure modes  |      |
|----------------|------|
| Short-circuits | 10 % |
| Open-circuits  | 90 % |

|   |   |                                     |
|---|---|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year  | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year   | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |   |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile. |                                     |

#### Mathematical formula for $\pi_t$

$$\pi_t = e^{\frac{2900}{303} \left( \frac{1}{273+t_A} - \frac{1}{273} \right)}$$

with  $t_A$  : ambient temperature

\* NOTE The following conditions must be respected to obtain field values in conformance with those calculated with the above formulas:

- For **radio interference suppression** capacitors the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,8**
- For other **non radio interference suppression** specified capacitors, this same ratio must be less or equal to **0,2**

with: peak voltage = continuous voltage + peak value of the alternative voltage

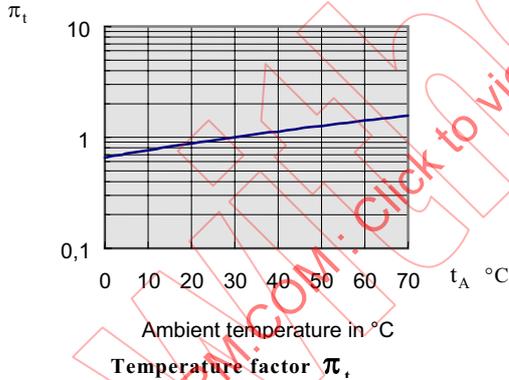
**10.2 Fixed ceramic dielectric capacitors – Defined temperature coefficient – Class I (IEC 60384)**

**MATHEMATICAL MODEL**

$$\lambda = 0.05 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 3.3 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note\*
- Peak value of the alternative voltage applied to the capacitor See note\*
- Rated voltage of the capacitor. See note\*



| Failure modes  |      |
|----------------|------|
| Short-circuits | 70 % |
| Open-circuits  | 10 % |
| Drifts         | 20 % |

|  |                 |                                     |
|--|-----------------|-------------------------------------|
| Mathematical expression of the Cycles/year | $n_i \leq 8760$ | $(\pi_n)_i = n_i^{0.76}$            |
| Influence factor $(\pi_n)_i$ Cycles/year   | $n_i > 8760$    | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |

$n_i$  : Annual number of cycles with the amplitude  $\Delta T_i$

|   |   |
|---|---|
| For an on/off phase                               | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$  |
| For a permanent working phase, storage or dormant | $\Delta T_i =$ average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile. |

**Mathematical formula for  $\pi_t$**

$$\pi_t = e^{\frac{1160}{303} \left( \frac{1}{273+t_A} - \frac{1}{273} \right)}$$

with  $t_A$  : ambient temperature

\* NOTE The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0.5**

with: peak voltage = continuous voltage + peak value of the alternative voltage

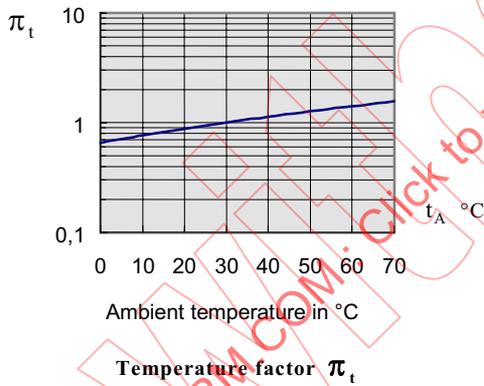
**10.3 Fixed ceramic dielectric capacitors – Non defined temperature coefficient – Class II – Radio interference suppression capacitors**

**MATHEMATICAL MODEL**

$$\lambda = 0.15 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 3.3 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

$t_{ae}_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.  
 $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.  
 $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.  
 $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.  
 $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$   
 $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.  
 $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .  
 $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.  
 Continuous voltage applied to the capacitor See note\*  
 Peak value of the alternative voltage applied to the capacitor See note\*  
 Rated voltage of the capacitor. See note\*



| Failure modes  | Other ceramic, class II capacitors | Radio interference suppression capacitors |
|----------------|------------------------------------|---|
| Short-circuits | 90 %                               | 70 %                                      |
| Open-circuits  | 10 %                               | 30 %                                      |

|   |   |                                     |
|---|---|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year  | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year   | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |   |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile. |                                     |

**Mathematical formula for  $\pi_t$**

$$\pi_t = e^{1160 \left( \frac{1}{303} - \frac{1}{273+t_A} \right)}$$

with  $t_A$  : ambient temperature

\* NOTE The following conditions must be respected, to obtain field values in conformance with those calculated with the above formulas:

- For **radio interference suppression** capacitors the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,8**
- For other **non radio interference suppression** specified capacitors, this same ratio must be less or equal to **0,5**

with: peak voltage = continuous voltage + peak value of the alternative voltage

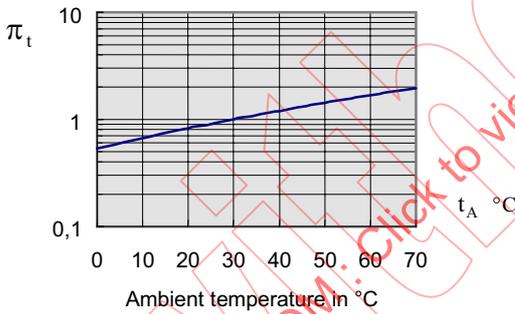
**10.4 Tantalum capacitors, solid electrolyte (IEC 60384)**

**MATHEMATICAL MODEL**

$$\lambda = 0.4 \times \left( \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 3.8 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $t_{ae,i}$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note 1
- Peak value of the alternative voltage applied to the capacitor See note 1
- Rated voltage of the capacitor. See note 1
- Situation of the capacitor See note 2



**Temperature factor  $\pi_t$**

| Mathematical formula for $\pi_t$   |
|--|
| $\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_A} \right)}$ with $t_A$ : ambient temperature |

| Failure modes  |      |
|----------------|------|
| Short-circuits | 80 % |
| Open-circuits  | 20 % |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

NOTE 1 The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

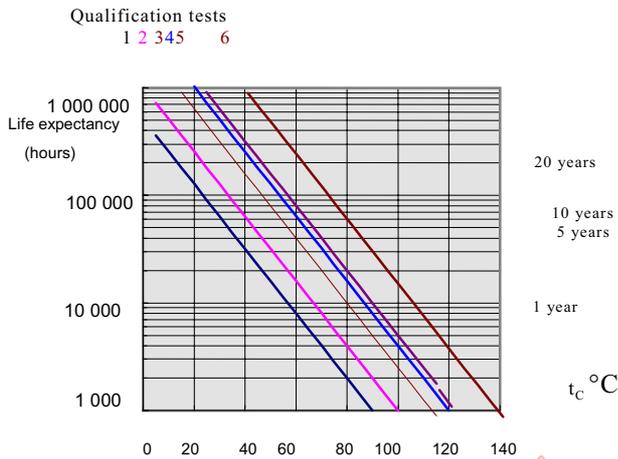
the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,5**

with: peak voltage = continuous voltage + peak value of the alternative voltage

NOTE 2 Caution must be taken against the risk of fire if the current is not limited (a fuse might be placed serially in one of the branches, between which the tantalum capacitor is positioned).

**10.5 Aluminum, non-solid electrolyte capacitors - Life expectancy**

Failure rate of non solid electrolyte aluminum capacitors is assumed to be constant but only within the life expectancy limits.



| Qualification test conditions (duration , temperature) According to capacitor types |              |                  |
|---|--------------|------------------|
| Qualification tests   | Duration (h) | Temperature (°C) |
| 1   | 1 000        | 85               |
| 2   | 2 000        | 85               |
| 3   | 5 000        | 85               |
| 4   | 2 000        | 105              |
| 5   | 10 000       | 85               |
| 6   | 2 000        | 125              |

**Life expectancy according to qualifications**

Test conditions of the capacitor

With:  $t_c$  : temperature of the capacitor, default value  

$$t_c = t_{\text{ambient}} + 5^\circ\text{C}$$

\*NOTE 1 Life expectancy depends on the operating temperature and on the qualification test conditions (i.e. on the technology type)  
 \*NOTE 2 Ambient temperature for a non solid electrolyte aluminum capacitor is taken at its immediate vicinity (overheating of the other components has to be taken into account).

**Mathematical formula for the life expectancy**

Life expectancy (hours) = qualification test duration  $\times 2^{\left(\frac{(T_M + 5) - T_c}{10}\right)}$   
 with  $T_M$  : maximum temperature of the climatic category

**MATHEMATICAL MODEL**

$$\lambda = 1.3 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \times \pi_A + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

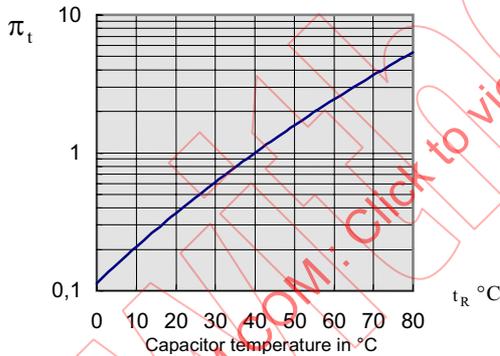
**NECESSARY INFORMATION:**

- $t_{ac,i}$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $\pi_A$  : factor related to the self heating
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.

Continuous voltage applied to the capacitor See note  
 Rated voltage of the capacitor. See note  
 Applied ripple current  
 Maximum admissible ripple current.

**CAUTION !**

Life expectancy of non solid electrolyte, aluminum capacitors is limited and very sensible to ambient temperature



Temperature factor  $\pi_t$

**Mathematical formula for  $\pi_t$**

$$\pi_t = e^{4640 \left( \frac{1}{313} - \frac{1}{273+t_R} \right)}$$

with  $t_R$  : capacitor temperature

**Capacitor temperature  $t_R$  °C:**

**CAUTION !**

The capacitor temperature is different to that of the ambient temperature if a current flows through the capacitor (particularly pulses for example) or if it is heated by a radiative environment (a dissipating component). It is necessary to:

- measure the case temperature,
- or, by default

⇒ take into account the heat dissipated by the radiative environment;

⇒ take into account the temperature rise  $\Delta t$  due to the current through the capacitor (self heating) by:

$$\Delta t = 20 \left( \frac{\text{Applied ripple current}}{\text{Maximum admissible current}} \right)^2$$

**Failure modes**

| Rated voltage  | < 350 V | ≥ 350 V |
|----------------|---------|---------|
| Short circuits | 30 %    | 50 %    |
| Open circuits  | 30 %    | 0 %     |
| Drifts         | 40 %    | 50 %    |

|   |                                |                                     |
|---|--------------------------------|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$ | $n_i \leq 8760$<br>Cycles/year | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year    | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |

$n_i$  : Annual number of cycles with the amplitude  $\Delta T_i$

|   |  |
|---|--|
| For an on/off phase                               | $\Delta T_i = \left[ \frac{T_R}{3} + (t_{ac})_i \right] - (t_{ac})_i$  |
| For a permanent working phase, storage or dormant | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |

**Peak value of the pulsed current**

| Ratio   |          | $\pi_A$ |
|---|----------|---------|
|   | ≤ 1,5    | 1       |
| Peak value of pulse current / Maximum admissible ripple current | 1,5 to 2 | 3       |
|   | 2 to 3   | 10      |

**NOTE** The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,5**

with: peak voltage = continuous voltage + peak value of the alternative voltage

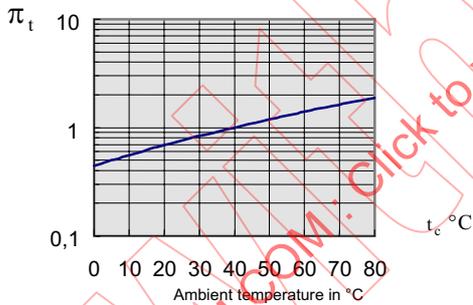
**10.6 Aluminum electrolytic capacitor, solid electrolyte**

**MATHEMATICAL MODEL**

$$\lambda = 2.4 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note
- Peak value of the alternative voltage applied to the capacitor See note
- Rated voltage of the capacitor. See note



**Temperature factor  $\pi_t$**

| Failure modes  |      |
|----------------|------|
| Short-circuits | 10 % |
| Open-circuits  | 90 % |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

| Mathematical formula for $\pi_t$   |
|--|
| $\pi_t = e^{1740 \left( \frac{1}{313} - \frac{1}{273+t_A} \right)}$ with $t_A$ : ambient temperature |

**NOTE** The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,8**

with: peak voltage = continuous voltage + peak value of the alternative voltage

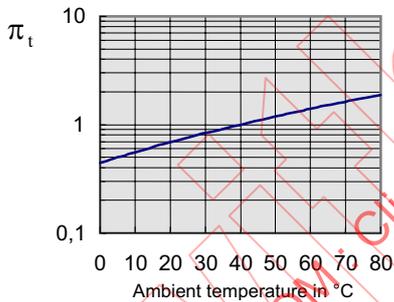
**10.7 Aluminum electrolytic capacitor, polymer electrolyte (IEC 60384)**

**MATHEMATICAL MODEL**

$$\lambda = 0.6 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 1.4 \times 10^{-3} \times \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $t_{ae}_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note
- Peak value of the alternative voltage applied to the capacitor See note
- Rated voltage of the capacitor. See note



**Temperature factor  $\pi_t$**

| Failure modes  |      |
|----------------|------|
| Short-circuits | 10 % |
| Open-circuits  | 90 % |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

| Mathematical formula for $\pi_t$   |
|--|
| $\pi_t = e^{1740 \left( \frac{1}{313} - \frac{1}{273+t_A} \right)}$ with $t_A$ : ambient temperature |

**NOTE** The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,8**

with: peak voltage = continuous voltage + peak value of the alternative voltage

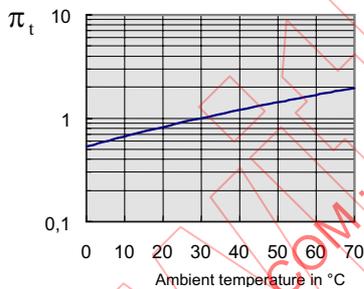
**10.8 Variable ceramic capacitors, disks (Dielectric ceramic) (IEC 60384)**

**MATHEMATICAL MODEL**

$$\lambda = 0.16 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 3.3 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the capacitor mission profile.
- $\tau_i$  :  $i^{emc}$  working time ratio of the capacitor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the capacitor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the capacitor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Continuous voltage applied to the capacitor See note
- Peak value of the alternative voltage applied to the capacitor See note
- Rated voltage of the capacitor. See note



Temperature model  $\pi_t$

| Failure modes  |      |
|----------------|------|
| Short-circuits | 40 % |
| Open-circuits  | 10 % |
| Drifts         | 50 % |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

| Mathematical formula for $\pi_t$   |
|--|
| $\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_A} \right)}$ with $t_A$ : ambient temperature |

NOTE: The following condition must be respected, to obtain field values in conformance with those calculated with the above formulas:

the ratio  $\frac{\text{peak voltage}}{\text{rated voltage}}$  must be less or equal to **0,5**

with: peak voltage = continuous voltage + peak value of the alternative voltage

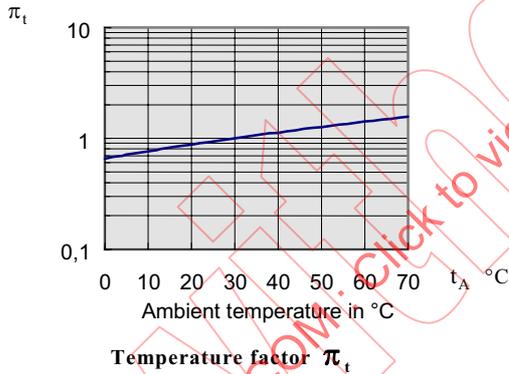
**10.9 Thermistors with negative temperature coefficient (NTC) (IEC 60539)**

**MATHEMATCAL MODEL**

$$\lambda = 3 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 2.7 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the thermistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the thermistor for the  $i^{ème}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the thermistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the thermistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the package, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.



| Mathematical formula for $\pi_t$ |  |
|----------------------------------|--|
| $\pi_t = e$                      | $1160 \left( \frac{1}{303 - 273 + t_A} \right)$ with $t_A$ : ambient temperature |

| Répartition des défauts |      |
|-------------------------|------|
| Short-circuits          | 70 % |
| Open-circuits           | 10 % |
| Drifts                  | 20 % |

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

**11 Resistors and potentiometers (IEC 60115)**

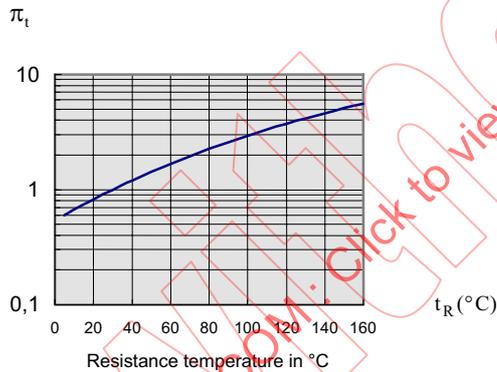
**11.1 Fixed, low dissipation film resistors – High stability (rs), general purpose (rc), “minimelf”**

**MATHEMATICAL MODEL**

$$\lambda = 0.1 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

$(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.  
 $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.  
 $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.  
 $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.  
 $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$   
 $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.  
 $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .  
 $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.  
 Power applied to the resistor.  
 Rated power of the resistor.

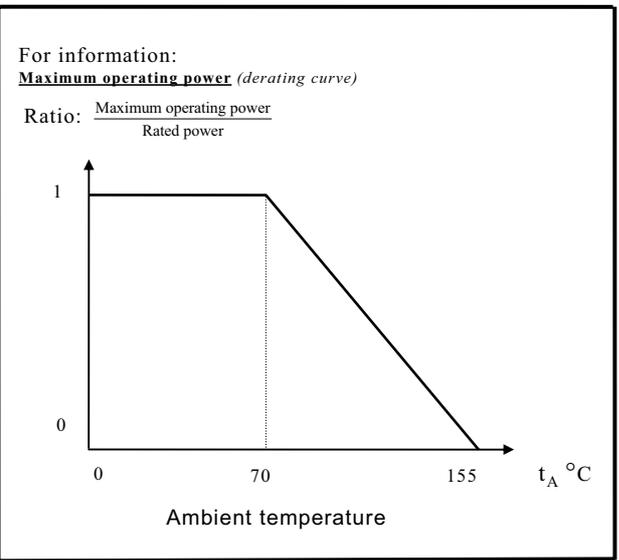


| Failure modes |      |
|---------------|------|
| Open-circuits | 40 % |
| Drifts        | 60 % |

**Mathematical formula for  $\pi_t$**

$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$  with  
 $t_R$  = Resistor temperature  
 $t_A$  = Ambient temperature  
 $t_R = t_A + 85 \times \frac{\text{Operating power}}{\text{Rated power}}$

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |



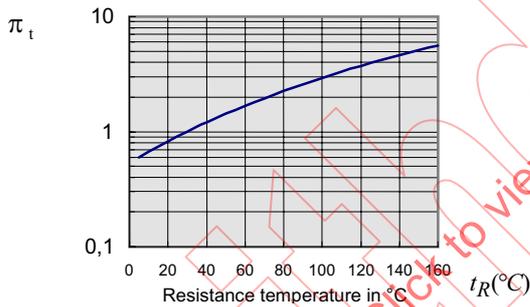
**11.2 Hot molded carbon composition, fixed resistors (IEC 60115)**

**MATHEMATICAL MODEL**

$$\lambda = 0.5 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Power applied to the resistor.
- Rated power of the resistor.



| Failure modes  |       |
|----------------|-------|
| Short-circuits | 0 %   |
| Open-circuits  | 100 % |

**Mathematical formula for  $\pi_t$**

with

- $t_R$  = Resistance temperature
- $t_A$  = Ambient temperature
- $t_M$  = maximum rated temperature

For  $t_M = 130^\circ\text{C}$

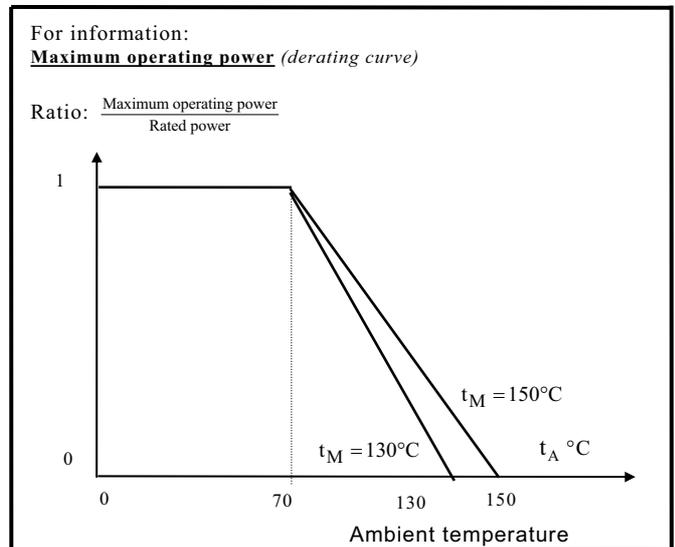
$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

$$t_R = t_A + 60 \times \frac{\text{Operating power}}{\text{Rated power}}$$

For  $t_M = 150^\circ\text{C}$

$$t_R = t_A + 80 \times \frac{\text{Operating power}}{\text{Rated power}}$$

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile |                                     |



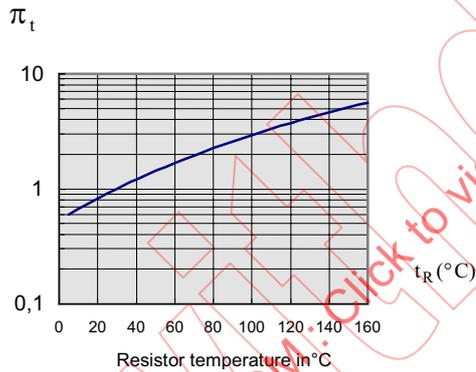
**11.3 Fixed, high dissipation film resistors (IEC 60115)**

**MATHEMATICAL MODEL**

$$\lambda = 0,4 \times \left( \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 1,4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0,68} \right] \right) \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Power applied to the resistor.
- Rated power of the resistor.



| Failure modes  |       |
|----------------|-------|
| Short-circuits | 0 %   |
| Open-circuits  | 100 % |

**Mathematical formula for  $\pi_t$**

with

- $t_R$  = Resistor temperature
- $t_A$  = Ambient temperature

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

$$t_R = t_A + 130 \times \frac{\text{Operating power}}{\text{Rated power}}$$

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0,76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1,7 \times n_i^{0,60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ (t_{ac})_i + \frac{t_R}{3} \right] - (t_{ae})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

For information:

**Maximum operating power** (derating curve)

Ratio:  $\frac{\text{Maximum operating power}}{\text{Rated power}}$

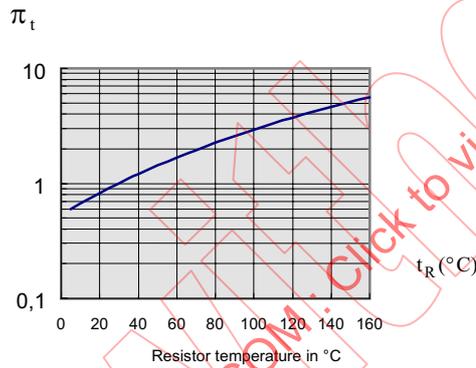
**11.4 Low dissipation wirewound resistors (IEC 60115)**

**MATHEMATICAL MODEL**

$$\lambda = 0.3 \times \left( \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 1.4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

$(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.  
 $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.  
 $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.  
 $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.  
 $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$   
 $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.  
 $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .  
 $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.  
 Power applied to the resistor.  
 Rated power of the resistor.



| Failure modes  |       |
|----------------|-------|
| Short-circuits | 0 %   |
| Open-circuits  | 100 % |

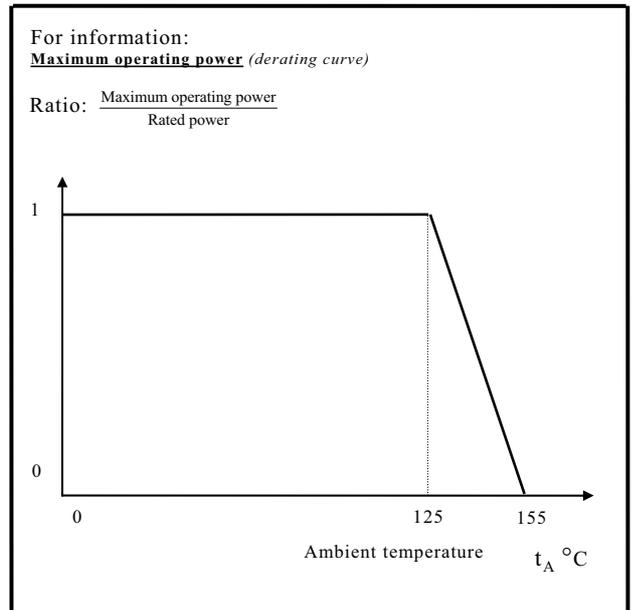
**Mathematical formula for  $\pi_t$**

with

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

$t_R$  = Resistor temperature  
 $t_A$  = Ambient temperature  
 $t_R = t_A + 30 \times \frac{\text{Operating power}}{\text{Rated power}}$

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile |                                     |



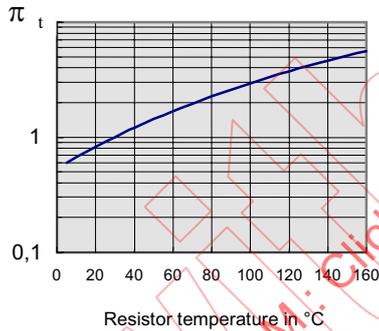
**11.5 High dissipation wirewound resistors (IEC 60115)**

**MATHEMATICAL MODEL**

$$\lambda = 0,4 \times \left( \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 1,4 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0,68} \right] \right) \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Power applied to the resistor.
- Rated power of the resistor.



| Failure modes  |       |
|----------------|-------|
| Short-circuits | 0 %   |
| Open-circuits  | 100 % |

**Mathematical formula for  $\pi_t$**

with

- $t_R$  = Resistor temperature
- $t_A$  = Ambient temperature
- $t_R = t_A + 130 \times \frac{\text{Operating power}}{\text{Rated power}}$

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0,76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1,7 \times n_i^{0,60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = \left[ (t_{ac})_i + \frac{t_R}{3} \right] - (t_{ae})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

For information:

**Maximum operating power** (derating curve)

Ratio:  $\frac{\text{Maximum operating power}}{\text{Rated power}}$

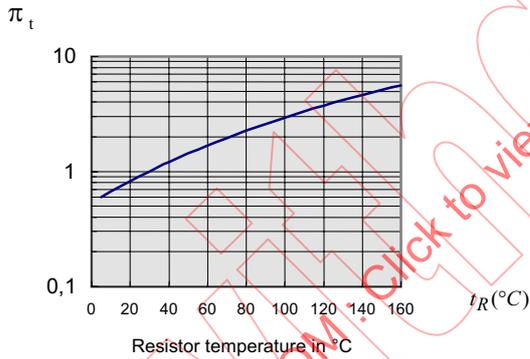
**11.6 Fixed, low dissipation surface mounting resistors and resistive array (IEC 60115)**

**MATHEMATICAL MODEL**

$$\lambda = 0.01 \times \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] \times \sqrt{N} + 3.3 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ae})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.
- $N$  : resistors number of the resistive array.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Power applied to the resistor.
- Rated power of the resistor..



|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

**Mathematical formula for  $\pi_t$**

with

- $t_R$  = resistor temperature
- $t_A$  = Ambient temperature
- $t_M$  = Maximum rated category ,

for  $t_M = 125^\circ\text{C}$

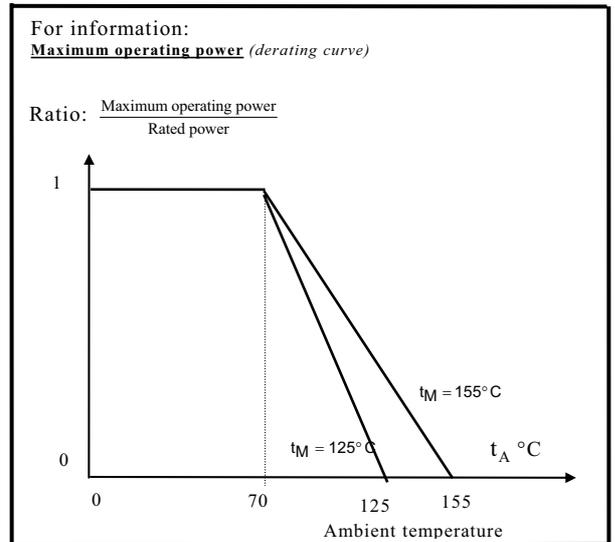
$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

$$t_R = t_A + 55 \times \frac{\text{Operating power}}{\text{Rated power}}$$

for  $t_M = 155^\circ\text{C}$

$$t_R = t_A + 85 \times \frac{\text{Operating power}}{\text{Rated power}}$$

| Failure modes |      |
|---------------|------|
| Drifts        | 60 % |
| Open-circuits | 40 % |



**11.7 Non wirewound cermet potentiometer (one or several turn) (IEC 60393)**

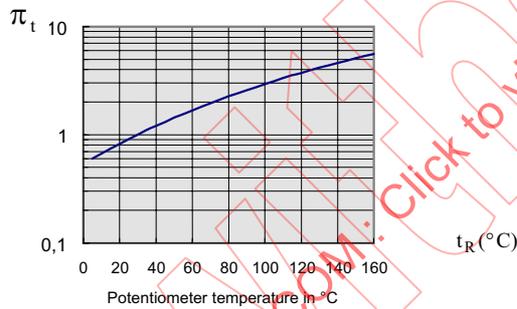
**MATHEMATICAL MODEL**

$$\lambda = 0.3 \times \left( \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right) \times \pi_Y + 1.2 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \times 10^{-9} / h$$

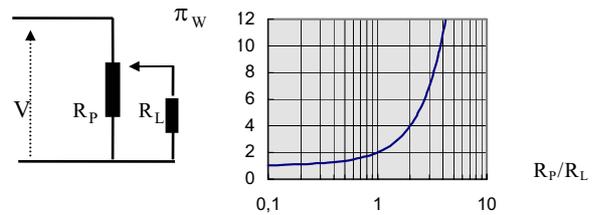
**NECESSARY INFORMATION:**

- $t_{ae}_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the resistor mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the resistor for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the resistor. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the resistor being in storage (or dormant) mode.
- $\pi_Y$  : factor related to the annual number of shaft rotation.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the resistor, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- $R_L$  and  $R_p$  for  $\pi_W$  calculation.
- Power applied to the resistor.
- Rated power of the resistor.

| Failure modes |      |
|---------------|------|
| Open-circuits | 80 % |
| Drifts        | 20 % |



| Number of annual shaft rotations |  | $\pi_Y$ |
|----------------------------------|--|---------|
| $\leq 10$                        |  | 0,2     |
| $> 10$                           |  | 1       |



**Mathematical formulas for  $\pi_t$ , and  $\pi_W$**

with

- $t_R$  = potentiometer temperature
- $t_A$  = ambient temperature
- $t_M$  = maximum rated temperature ,

for  $t_M = 125^\circ\text{C}$

$$\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$$

and

$$\pi_W = 1 + \frac{1}{2} \left[ \frac{R_p^2}{4R_L^2} + \frac{R_p}{R_L} \right]$$

for  $t_M = 155^\circ\text{C}$

$$t_R = t_A + 55 \times \frac{\frac{V^2}{R_p} \times \pi_W}{\text{Rated power}}$$

for  $t_M = 155^\circ\text{C}$

$$t_R = t_A + 70 \times \frac{\frac{V^2}{R_p} \times \pi_W}{\text{Rated power}}$$

**For information:**

**Maximum operating power (derating curve)**

Ratio:  $\frac{\text{Maximum operating power}}{\text{Rated power}}$

|   |   |                                     |
|---|---|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year  | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year   | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |   |                                     |
| For an on/off phase   | $\Delta T_i = (t_{ac})_i - (t_{ae})_i$  |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ae})$ variation, during the $i^{\text{th}}$ phase of the mission profile |                                     |

IECNORM.COM: Click to view the full PDF of IEC TR 62380:2004

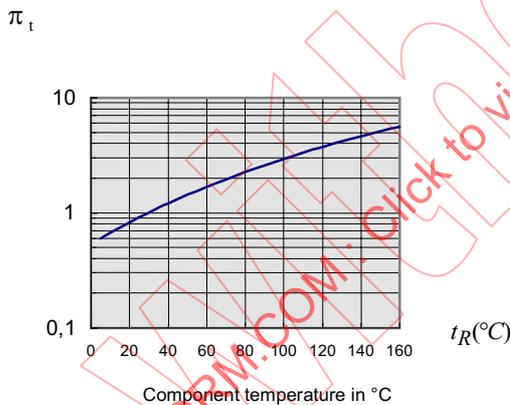
12 Inductors and transformers (IEC 61248)

**MATHEMATICAL MODEL**

$$\lambda = \lambda_0 \times \left( \left[ \frac{\sum_{i=1}^y (\pi_t)_i \times \tau_i}{\tau_{on} + \tau_{off}} \right] + 7 \times 10^{-3} \times \left[ \sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times 10^{-9} / h$$

**NECESSARY INFORMATION:**

- $(t_{ac})_i$  : average outside ambient temperature surrounding the equipment, during the  $i^{th}$  phase of the mission profile.
- $(t_{ac})_i$  : average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled.
- $(\pi_t)_i$  :  $i^{th}$  temperature factor related to the  $i^{th}$  junction temperature of the component mission profile.
- $\tau_i$  :  $i^{th}$  working time ratio of the component for the  $i^{th}$  junction temperature of the mission profile.
- $\tau_{on}$  : total working time ratio of the component. With:  $\tau_{on} = \sum_{i=1}^y \tau_i$
- $\tau_{off}$  : time ratio for the component being in storage (or dormant) mode.
- $(\pi_n)_i$  :  $i^{th}$  influence factor related to the annual cycles number of thermal variations seen by the component, with the amplitude  $\Delta T_i$ .
- $\Delta T_i$  :  $i^{th}$  thermal amplitude variation of the mission profile.
- Power lossed by the component.
- Radiating surface of the component.



|   |  |                                     |
|---|--|-------------------------------------|
| Mathematical expression of the Influence factor $(\pi_n)_i$     | $n_i \leq 8760$<br>Cycles/year   | $(\pi_n)_i = n_i^{0.76}$            |
|   | $n_i > 8760$<br>Cycles/year  | $(\pi_n)_i = 1.7 \times n_i^{0.60}$ |
| $n_i$ : Annual number of cycles with the amplitude $\Delta T_i$ |  |                                     |
| For an on/off phase of a power inductor                         | $\Delta T_i = \left[ (t_{ac})_i + \frac{t_R}{3} \right] - (t_{ac})_i$  |                                     |
| For an on/off phase of a low current inductor                   | $\Delta T_i = (t_{ac})_i - (t_{ac})_i$   |                                     |
| For a permanent working phase, storage or dormant               | $\Delta T_i$ = average per cycle of the $(t_{ac})$ variation, during the $i^{th}$ phase of the mission profile |                                     |

| Mathematical formula for $\pi_t$                                    |  |
|---|--|
| $\pi_t = e^{1740 \left( \frac{1}{303} - \frac{1}{273+t_R} \right)}$ | with:<br>$t_R$ = component temperature<br>$t_A$ = ambient temperature around component<br>$t_R = t_A + 8.2 \times \frac{\text{Power loss (watt)}}{\text{Radiating surface (dm}^2\text{)}}$ |

| Failure rates according to the component type (FIT) |  |          | $\lambda_0$ |
|---|--|----------|-------------|
| Inductors   | Low current inductors                        | fixed    | 0,2         |
|   |  | variable | 0,4         |
|   | Power inductors (50 Hz, chopping, filtering) |          | 0,6         |
| Transformers  | Signal transformers                          |          | 1,5         |
|   | Power transformers                           |          | 3           |

| Failure modes  |      |
|----------------|------|
| Short-circuits | 20 % |
| Open-circuits  | 80 % |